



ELECTRONICS AT THE CORE OF THE AUTONOMOUS, CONNECTED AND ELECTRIFIED VEHICLES REVOLUTION

<https://www.youtube.com/watch?v=Bg8zw1SWiJA&feature=youtu.be>

<https://www.youtube.com/watch?v=2Y7uLbpehcQ&list=PL13CyHsHfOt1GC19RsPv-FvITnbbnd2e0&index=7>



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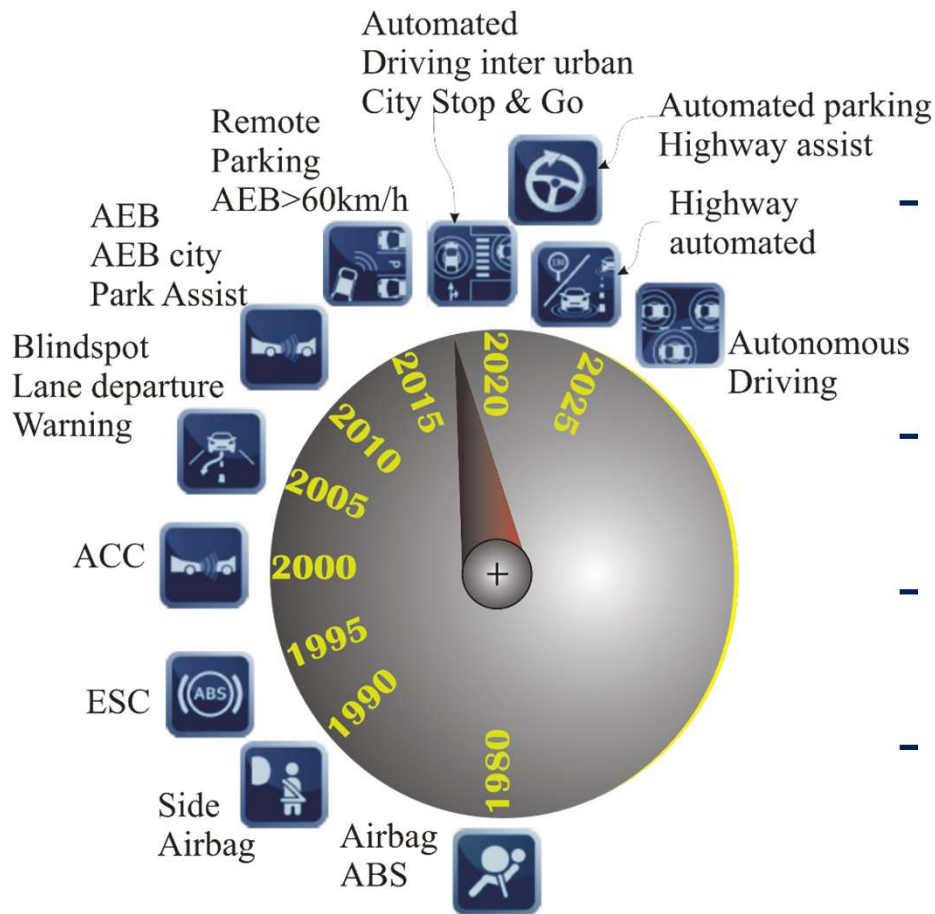


Outline

- Trends in smart vehicles & intelligent transport systems (ITS) and impact for society/economy
- University pillars: opportunities for continuous education, R&D, and technology transfer in Electronics
- Example R&D case studies:
 - Integrated Power Converters for 48 V micro/mild-hybrid vehicles
 - ITS surveillance X-band Radar
 - Cybersecurity acceleration

Trends in smart vehicles and ITS

A research theme of **high economical and social impacts**



- **Improving safety** (1.3M killed people/year worldwide**, 3.2k/year killed & 242k/year injured in Italy***)
- **Reducing CO2** (diesel-gate cost 31.3 Billions for carmakers*)
- **Improving life conditions with less pollution/traffic-jam**
- **Improving user experience** (comfort, digital lifestyle, status symbol, inclusive mobility for all, HMI, infotainment)
- **High economic value** (70M of new vehicles/year#, 40M of e-bikes/year sold worldwide##)

***https://www.istat.it/it/files//2020/07/Road-accidents_2019_EN.pdf

**<https://www.who.int/news-room/fact-sheets/detail/road-traffic-injuries>

*<https://www.reuters.com/article/us-volkswagen-results-diesel-idUSKBN2141JB>

#<https://www.statista.com/statistics/200002/international-car-sales-since-1990/>

##<https://www.bike-eu.com/market/nieuws/2020/01/deloitte-study-e-bike-sales-in-2023-at-40-million-units-generating-19-billion-euro-10137172>

Trends in smart vehicles and ITS

ACE: vehicles are becoming Autonomous, Connected, Electrified

Spin-off of the research results towards Robotics, Industry4.0, Logistics, Avionics, Energy Management...

Huge investments from Semiconductor and ICT companies and joint alliances with Tier-1&OEM car companies (e.g. INTEL-BMW, FCA-Google, NVIDIA-Bosch-VW-Continental)

INTEL (\$15.3 billion Mobileye acquisition) estimates the vehicle systems, data and services market per year to be up to \$70 billion by 2030*

VW group committed to \$86 billion investments in 5 years in electrified and digital vehicles**

**<https://www.reuters.com/article/volkswagen-strategy-idUSKBN27T24O>

*<https://newsroom.intel.com/news-releases/intel-mobileye-acquisition/#gs.56yyyye>

ICT-Automotive industry alliances

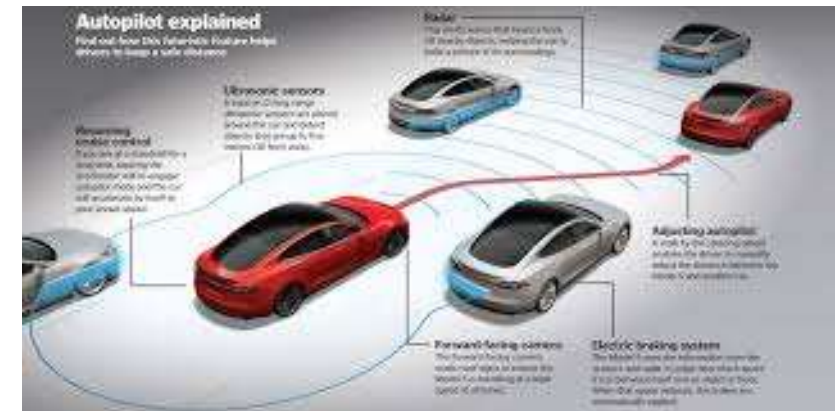
BMW
GROUP



Rolls-Royce
Motor Cars Limited



FCA
FIAT CHRYSLER AUTOMOBILES



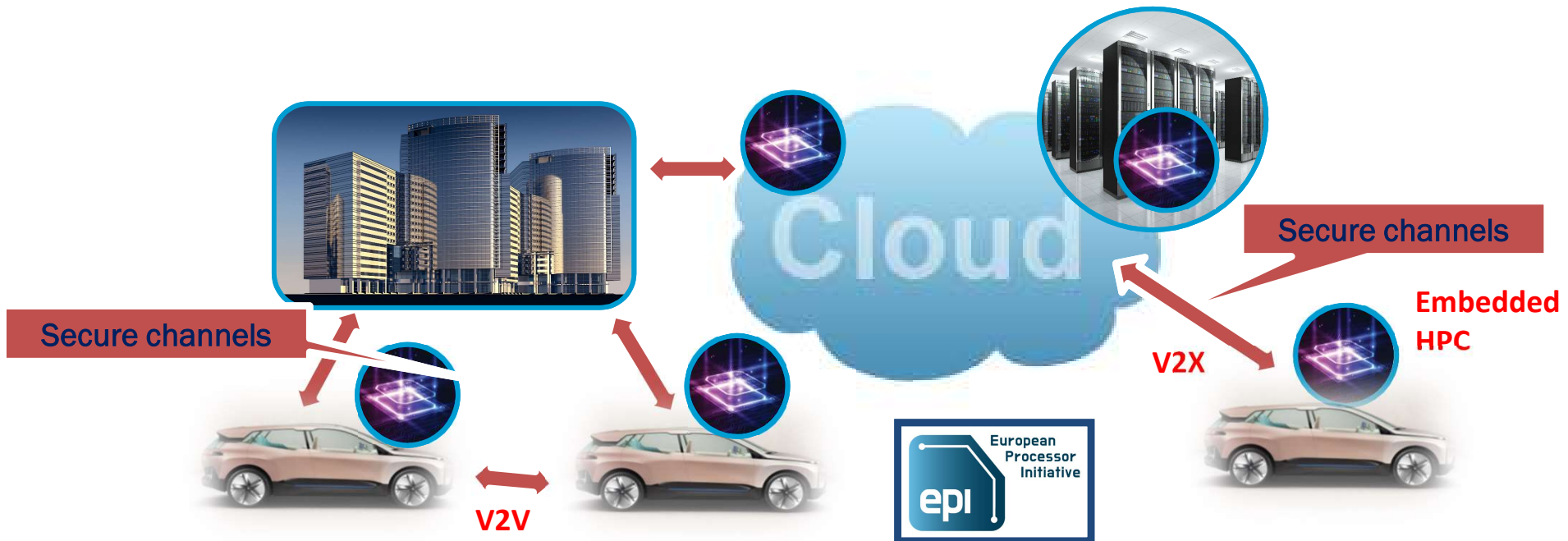
**New CEO of Ferrari (iconic car brand) from an Electronics company
(B. Vigna from STMicroelectronics)**

<https://www.ferrari.com/en-EN/articles/ferrari-appoints-benedetto-vigna-as-chief-executive-officer>

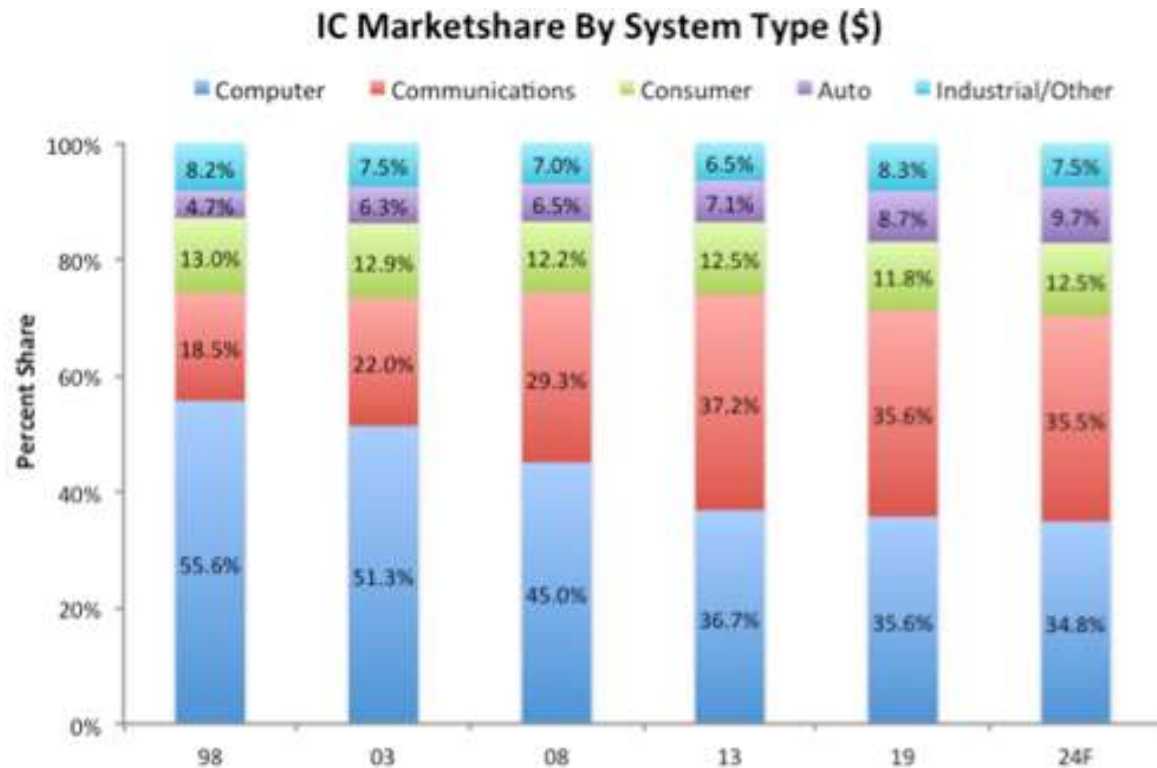
ICT-Automotive industry alliances

5GAA

Association



Automotive ICs market trends



Source: IC Insights

**The big dilemma:
Assisted driving or fully autonomous driving?**

100% safety not possible

What is possible? a statistics of incidents, injured/died people in favour of ADAS

Beware of legal issue!!!!

Beware of psychological issues!!!!

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Vehicle as a platform for pervasive R&D in Electronics

RF & mmWaves

(mmW Radar, 802.11p/bd V2X, 5G C-V2X, GNSS)

Sensors AFE & signal processing

(Image, Radar, Lidar, Ultrasonics, IMU,..& fusion in real-time)

Power Electronics

(SiC&GaN devices, DC/DC converters, inverters, on-board chargers, 12V→48V→400V→800V, energy storage&BMS)

digital twin, RT
robust & embedded
control

Opto-electronics

(Low-cost Lidar, high-speed networking, FBG sensors, lights/display, SiPh)



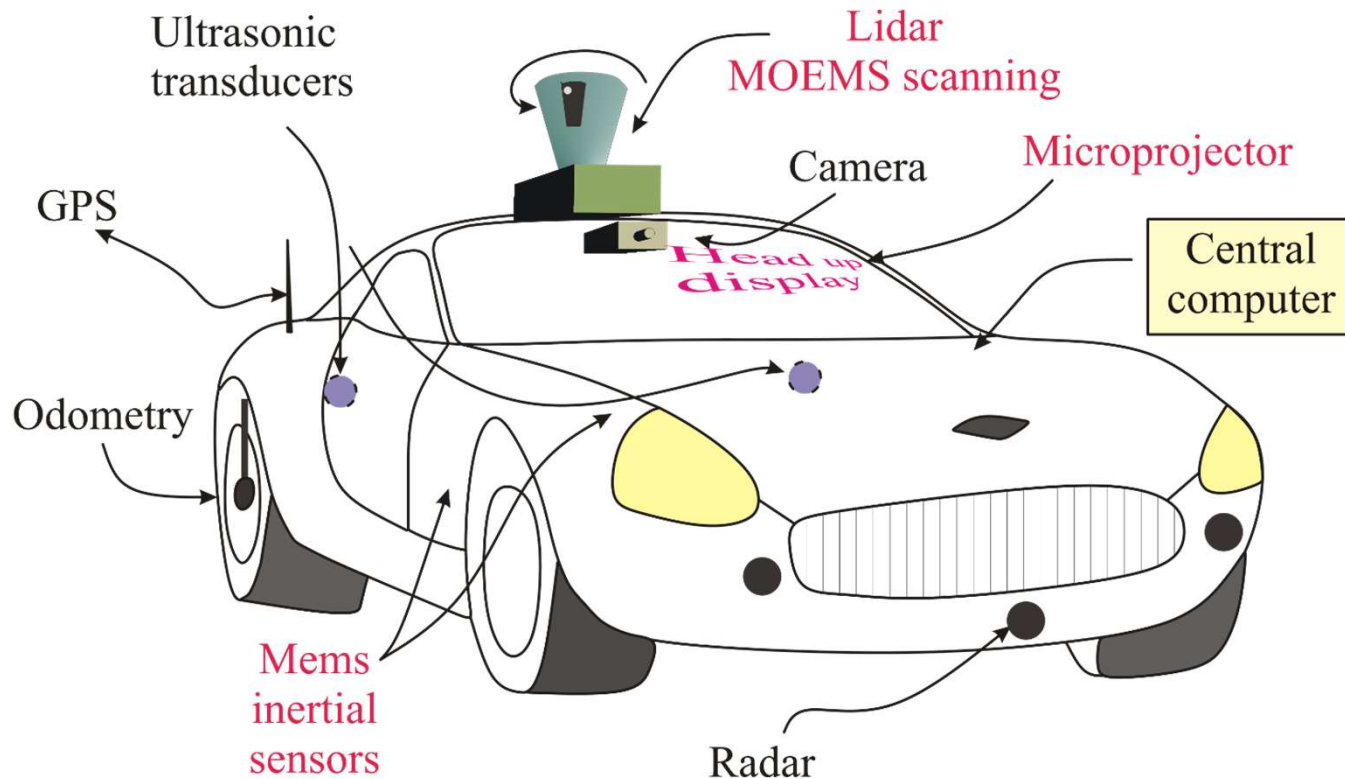
Predictive-diagnostic

(thermal, EMI/EMC, electrical, ageing, vibrations,..)
for functional safety

Sensors device &
technologies (MEMS/MOEMS)

eHPC & memories (multi-core, AI & security accelerators, high SIL in harsh environments)

Example: Sensing & Measurement Perspective



What?

obstacle detection

Where?

position and direction of cars and obstacles

When?

car to obstacle relative speed

Measurement Performance

range, resolution and accuracy of distance, angles & speed?

reliable (**uncertainty, repeatability**) measures in harsh environment ?

secure (**trusted, identified, private**) measures?

sustainable (low-power, low-cost, life-cycle)

Scientific R&D funding

FP7 ATHENIS-3D (2013-2017) *Automotive tested high-voltage and embedded non-volatile integrated SoC platform with 3D technology, EU project funds 6 M€, UNIFI funds 0.3 M€, UNIFI leadership* **WP5 Test chip development**



H2020 Hiefficient (2021-2024) *Highly EFFICIENT and reliable electric drivetrains based on modular, intelligent and highly integrated WBG power electronics modules, project budget 42 M€, UNIFI budget 0.45 M€, UNIFI leadership* **T3.3 Digital twin WBG-based power converters**



H2020 EPI (2018-2021) *European Processor Initiative, EU project funds 80 M€, UNIFI funds 1.55 M€, UNIFI leadership* **WP9 Cybersecurity**



H2020 TEXTAROSSA (Apr 2021-2024): *Towards EXtreme scale Technologies and Accelerators for euROhpc hw/Sw Supercomputing Applications for exascale, lead of CINI (budget 1.2 M€, UNIFI linked part), project budget 6M€, UNIFI leadership* **WP2 IP accelerators (AI, mixed-precision&posits, cybersecurity)**



H2020 The European Pilot (1 Oct 2021-2024): *Pilot using Independent Local & Open Technologies, lead of CINI (budget 1 M€, UNIFI linked part), project budget 30M €*

Continuous Education

Electrification and digitization of vehicles and ITS → needs of

New (young, 25-30 yrs) engineers expert in vehicular electronics

(device, circuit, system levels; analog, digital; ele & opto) not only in semiconductor industry but mainly in mechanic/mechatronic companies

→ new L8/LM29 (or simply, new curricula in current Electronics Eng.), degrees (e.g. Embedded Mechatronics)

→ more electronics courses in industrial engineering degrees (HW & embedded security LM Cybersecurity, Vehicular Electronics in LM Vehicle Eng., Electronic System for Robotics in LM Robotics and Control Engineering)

Re(Up)skilling of employees (35-55 yrs) with industrial eng. background

Specific short courses (50-100 h/class)

(co-funds available from EU & local institutions; consolidating job positions)

New opportunities available from the PNRR

(Missione 3: infrastrutture per mobilità sostenibile; Missione 2: rivoluzione verde e transizione ecologica)

Continuous Education

<https://www.continental.com/en/press/press-releases/2021-01-22-qualification-campaign-246248>

Automotive Electronics & Powertrain Electrification

12 CFU Corso Perfezionamento, S. Saponara director, re-skill course for 100 Engineers of Vitesco (Continental), 4 classes, 645 h/14 teachers, 200k€ funding, Confindustria/Reg. Toscana support

2 international summer schools about 5G (1 edition) and IoT (7 editions, 2 times co-funded by IEEE CAS seasonal school scheme) including circuits&systems vehicular connectivity lectures



New proposal **"e-Mobility: Digital & Electrified Products & Systems"**, 150k€, Pierburg, Magna, Azimuth Benetti, Wass (Leonardo), CNA/Comune Livorno/Regione Toscana support

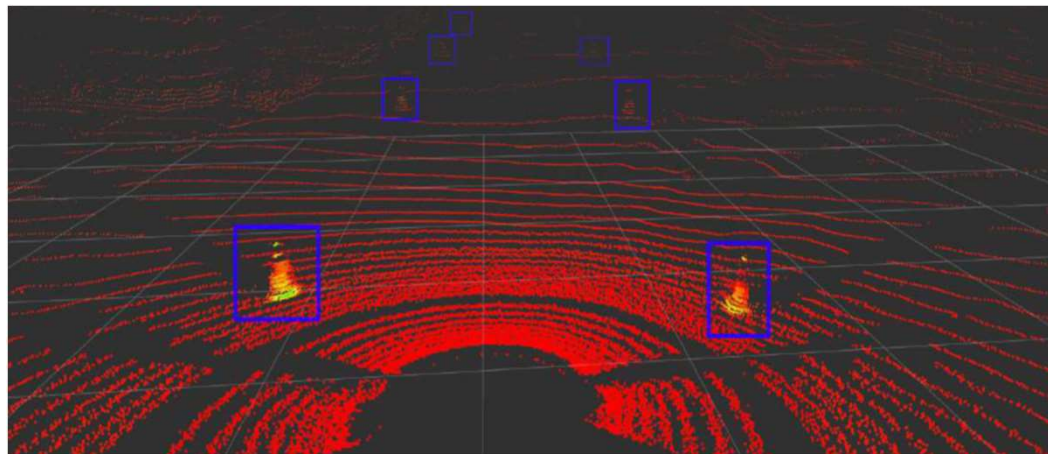
Initiatives for students on vehicles at UNIPISA



Association of Universities + Institutions + 15 Industries operating in Tuscany

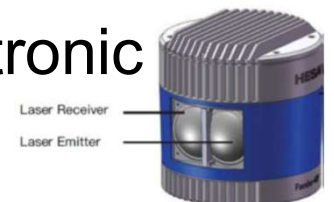


Formula SAE
(Kerub car)



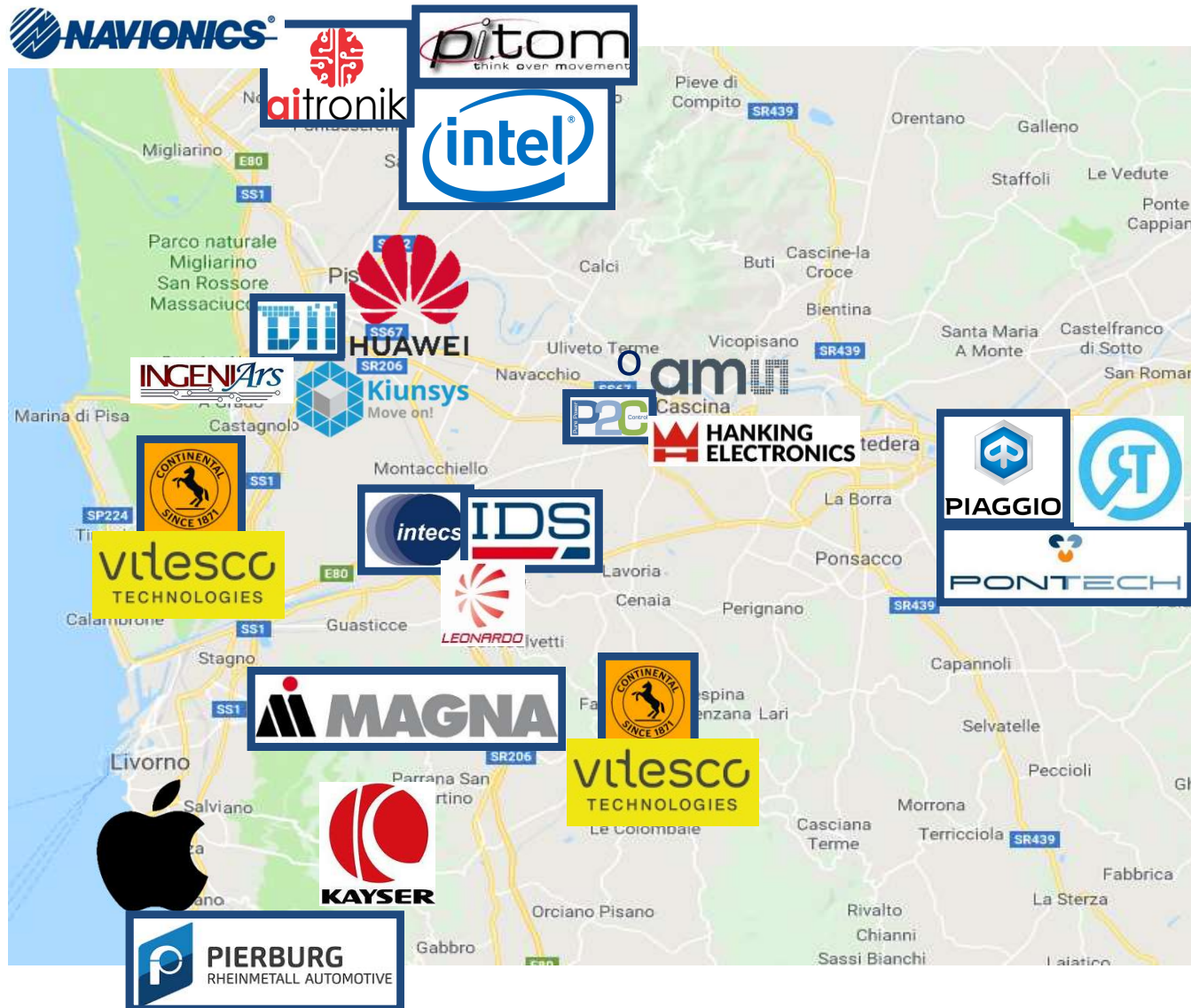
Since 2021 Formula SAE driverless (e.g. cone-recognition with Pandar 40 lidar)

6 Students from Electronic Engineering



Attract new investments in Italy (the Pisa-Livorno Area case study)

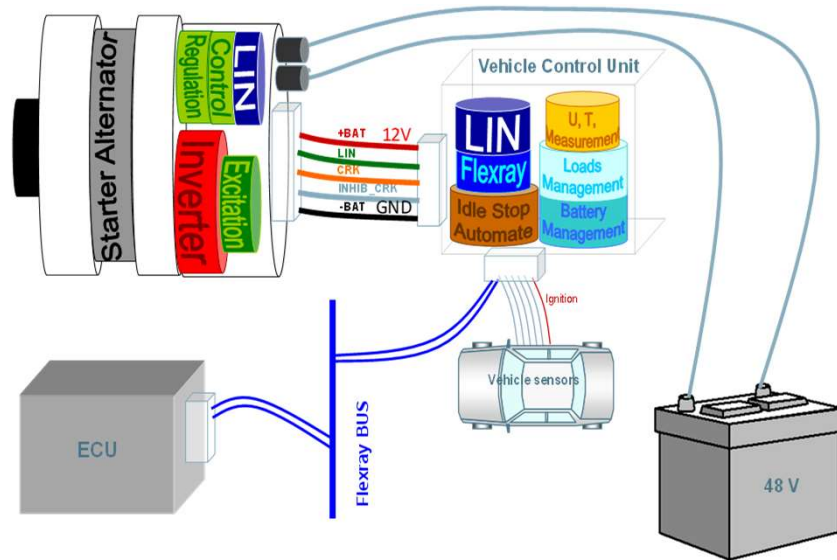
<http://www.movet.org/toscana-valley-anche-le-major-hi-tech-lapprezzano/>



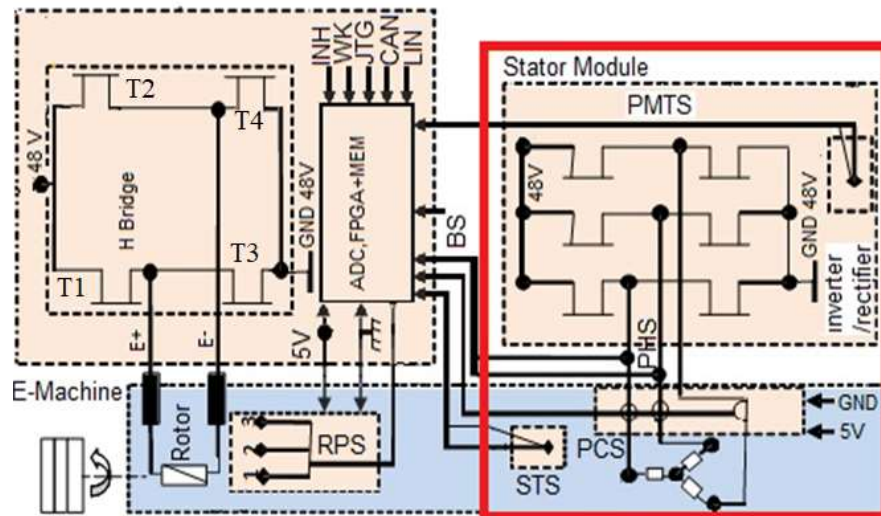
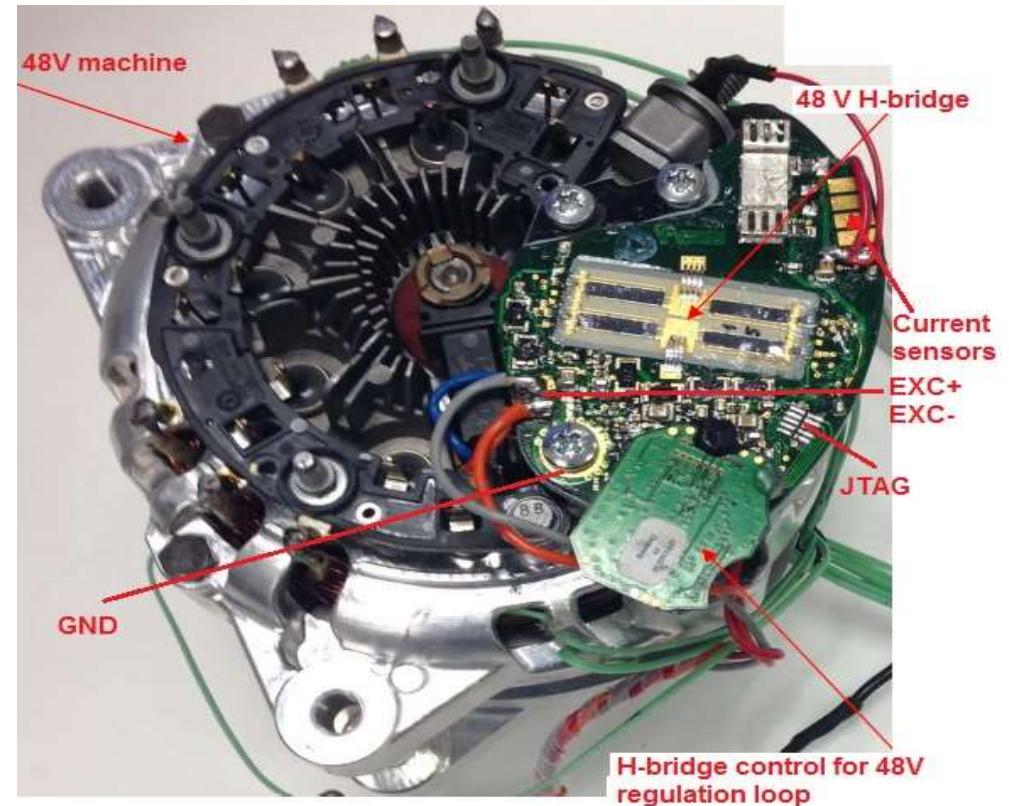
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Integrated Power Converters for 48 V micro/mild-hybrid vehicles



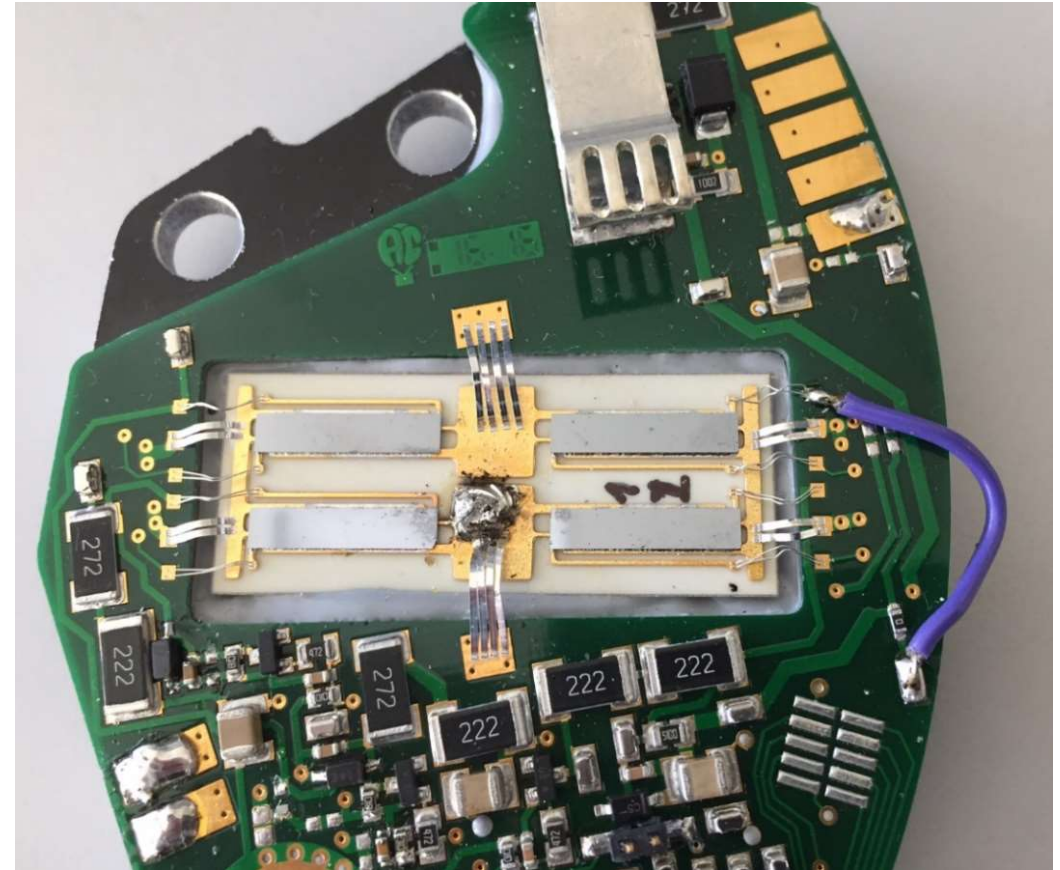
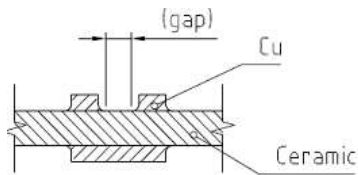
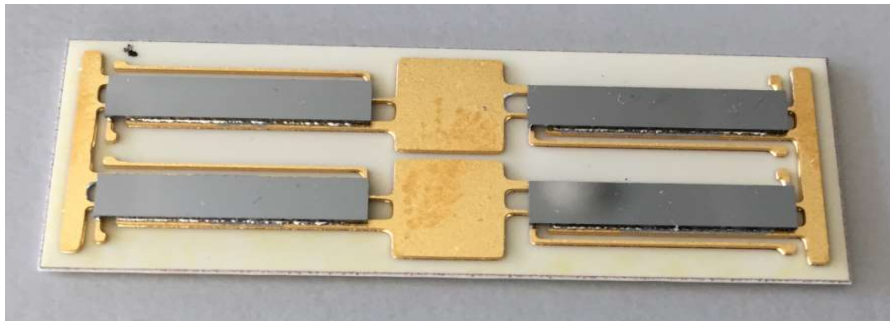
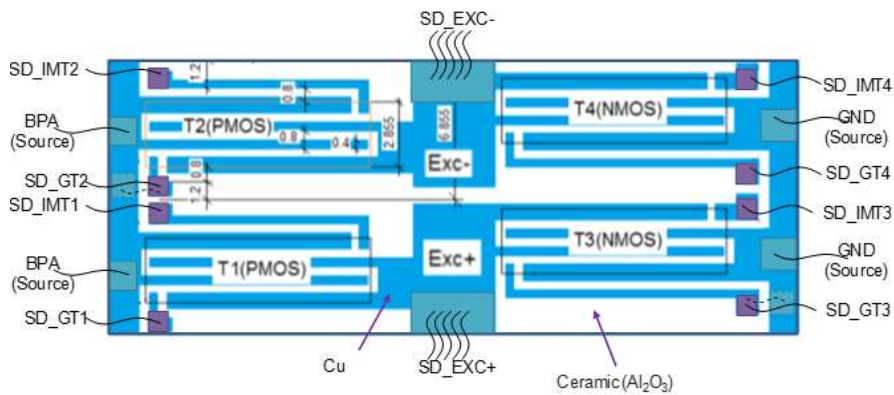
Electric Drives and Power Chargers: Recent Solutions to Improve Performance and Energy Efficiency for Hybrid and Fully Electric Vehicle, IEEE Vehicle Tech. Mag. 2020



**Collaboration with
Valeo & AMS in FP7 Athenis3D
MIT in MISTI seed fund scheme**

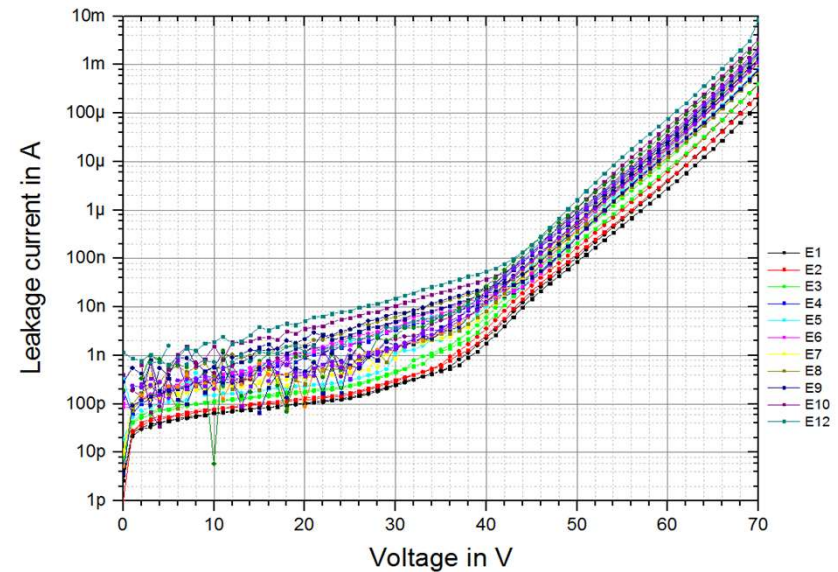
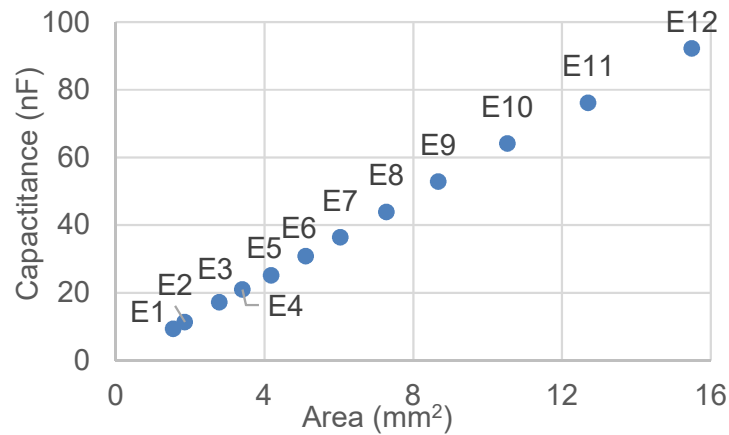
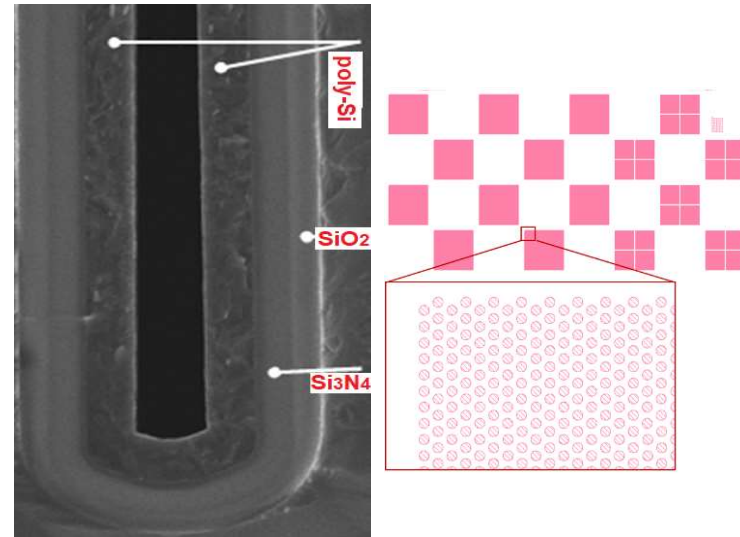
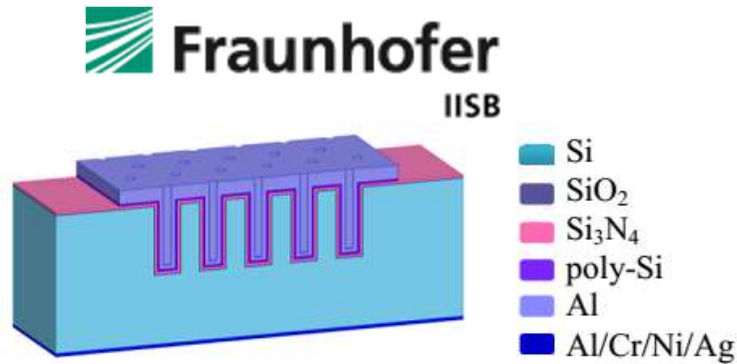


48 V power bridge in 180 nm HV MOS



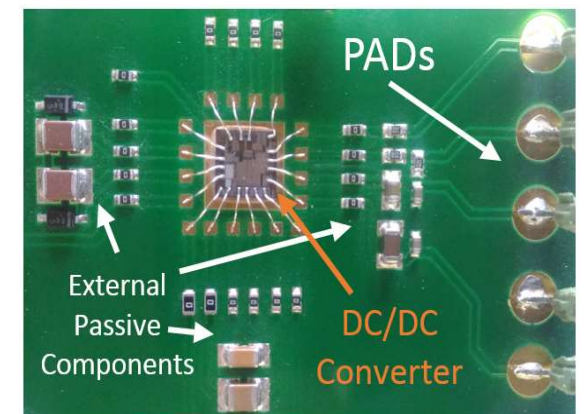
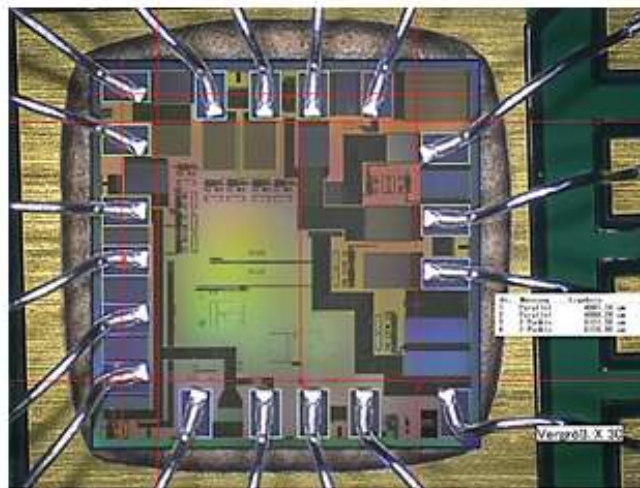
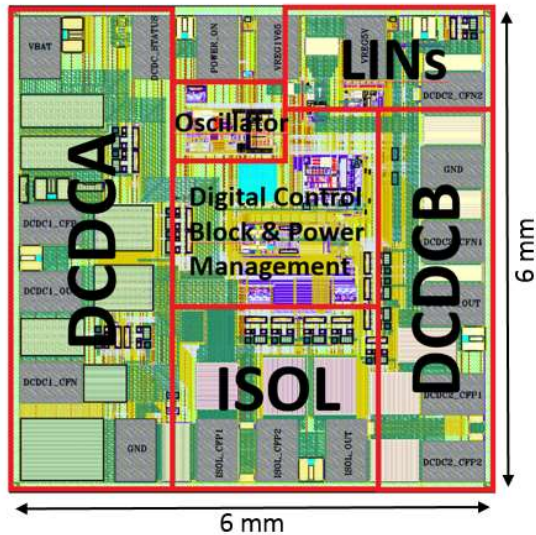
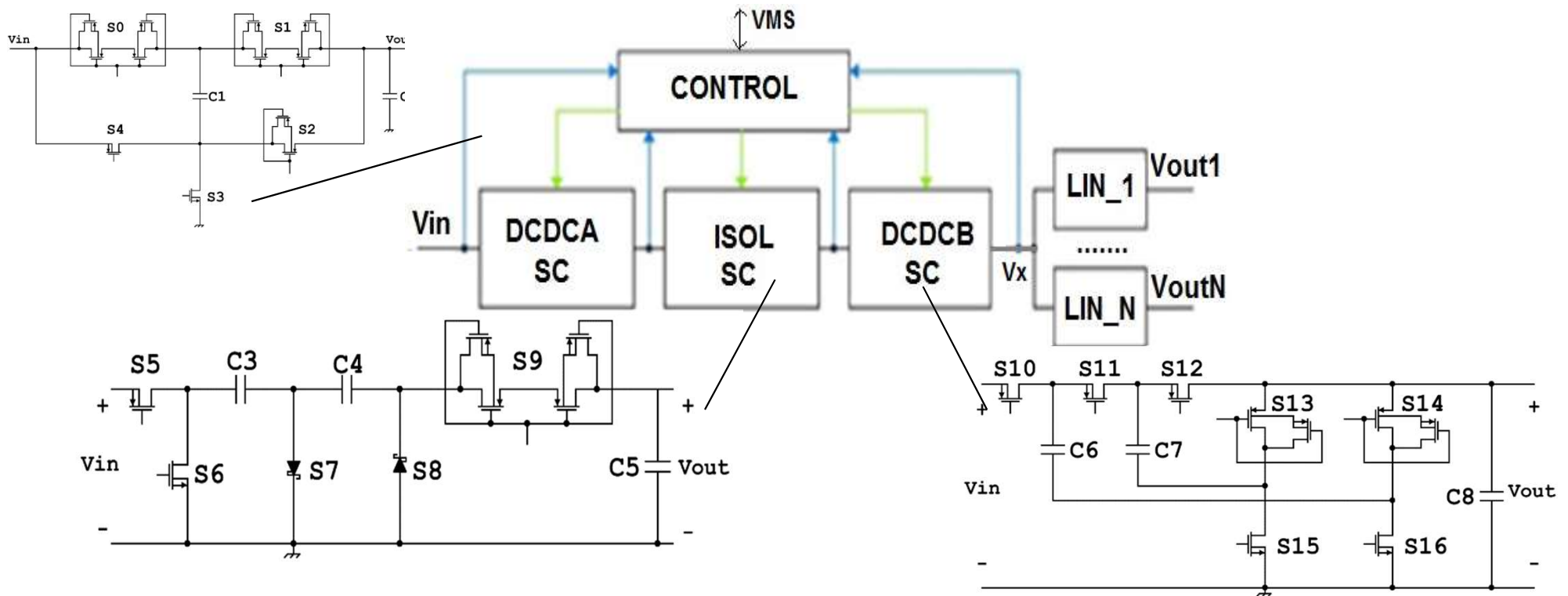
Direct bonded copper to reduce on-resistance

Integrated silicon-TSV HV capacitors

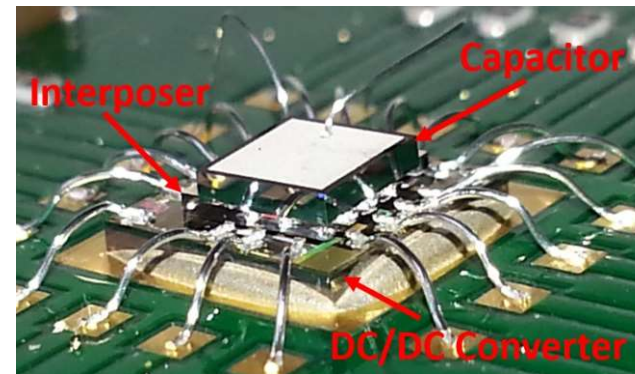
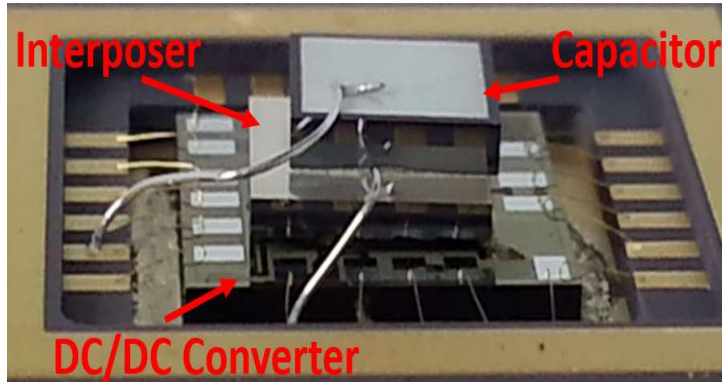


Integrated MOS-compliant power capacitors up to 70 V

48 V Switched-Cap (SC) architecture

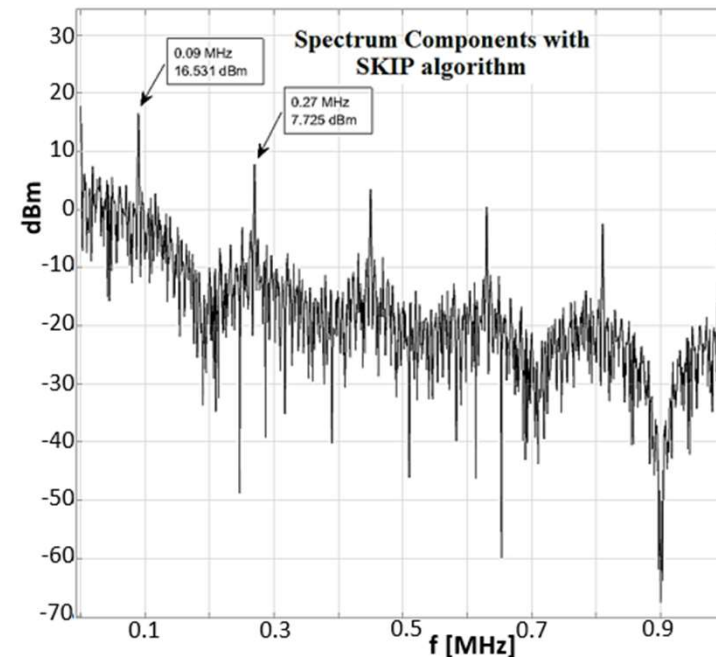
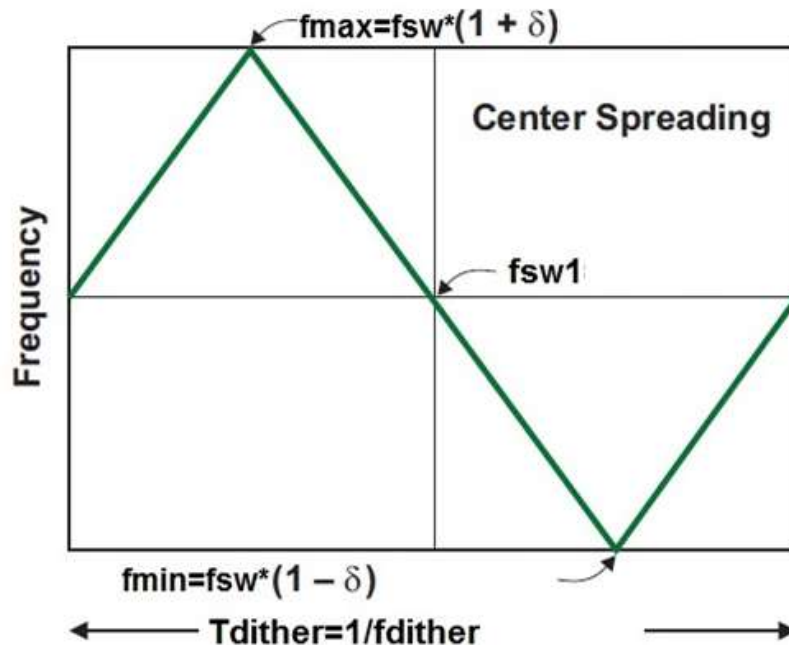


with capacitors stacked on top

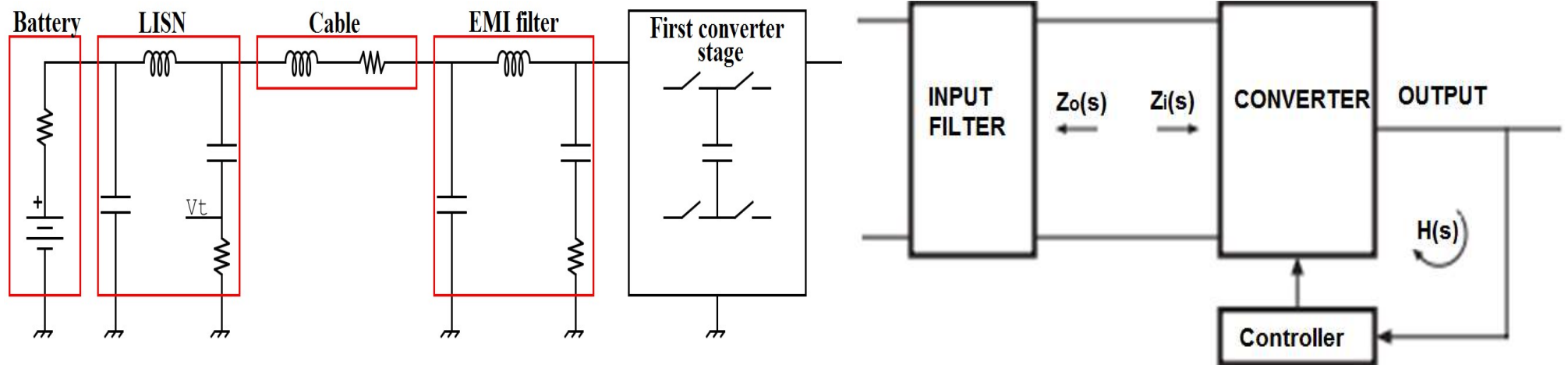


Similar performance of 3D vs. 2D but much lower area

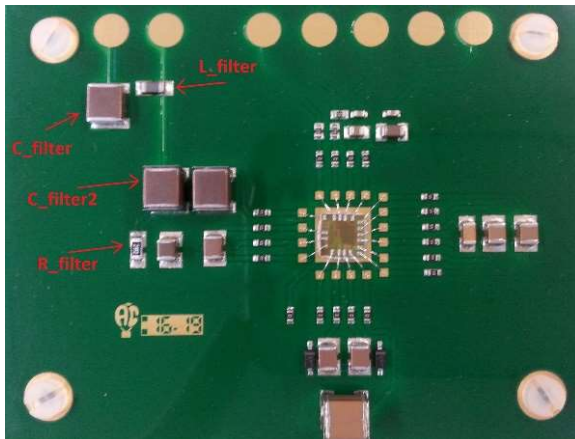
6 dB reduction of the EM Interference power emission thanks to SKIP-mode
*Extra spectral attenuation with fsw spreading (dB) = 10 * log[(f_{SW} * δ) / (f_{DITHER} / n)]*



Anti-EMI filter



The design of anti-EMI filter aware of input converter impedance reduces x 3 the size of the filter components and avoids instability

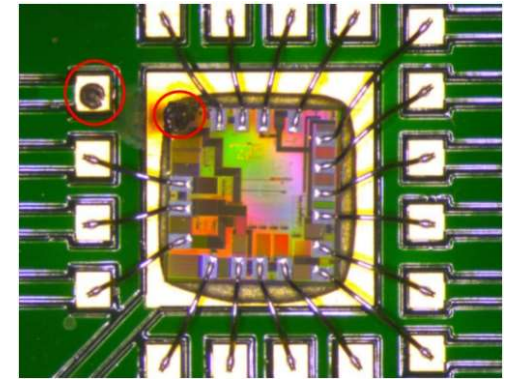
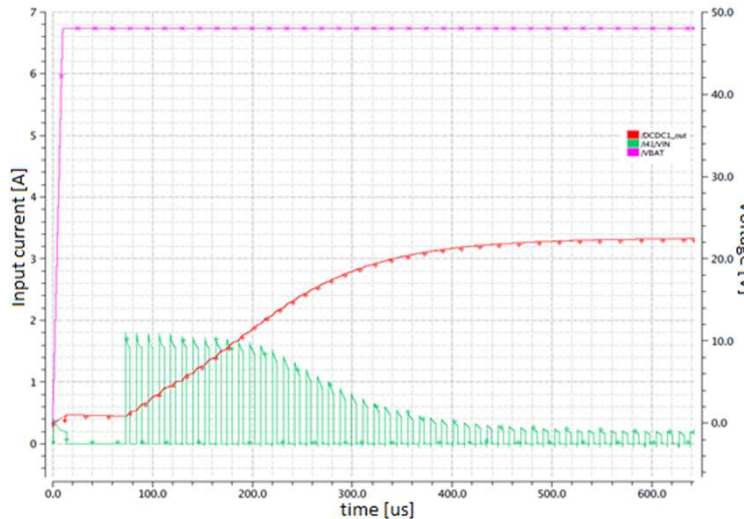
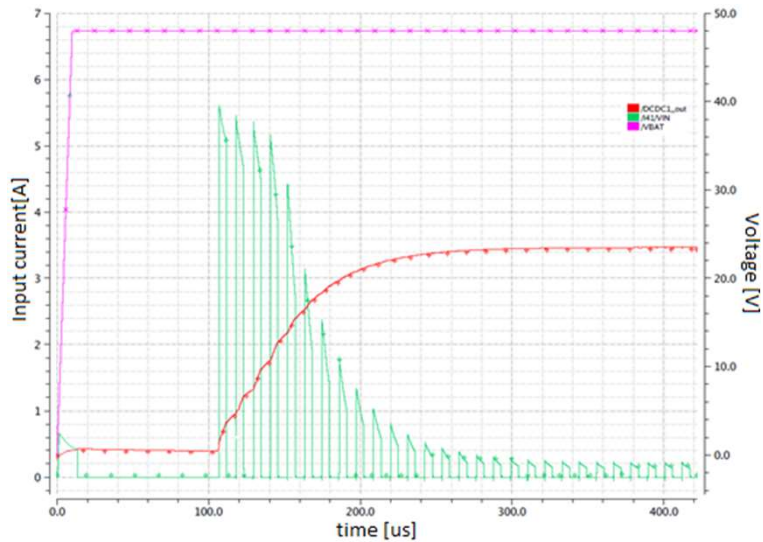


	Set-up		EMI measurement results	
	$V_{battery}$, [V]	I_{load} , [mA]	Freq. peak., [kHz]	Amplitude, [dBV]
This work	8	0-300	180	-84, -74.8, -65.4
	12	0-300	180	-87.2, -77.4, -69.8
	24	0-300	180	-77.8, -77.2, -75.4
	48	0-300	160	-74.4, -76.4, -71.4
	60	0-300	100	-71.4, -63, -57.8
[TI]	30	1600	10	-47.5

Soft-start

Input current without/with soft-start modality (current peaks reduced by 3 times).

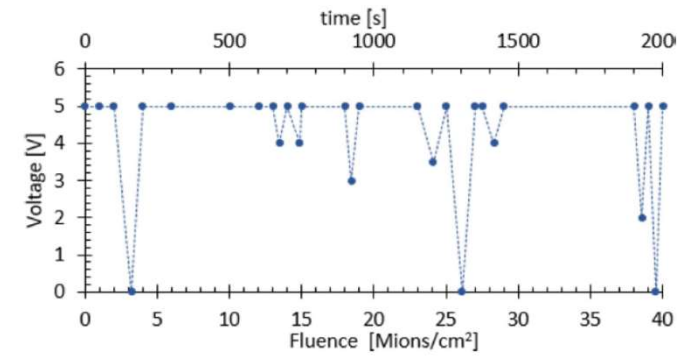
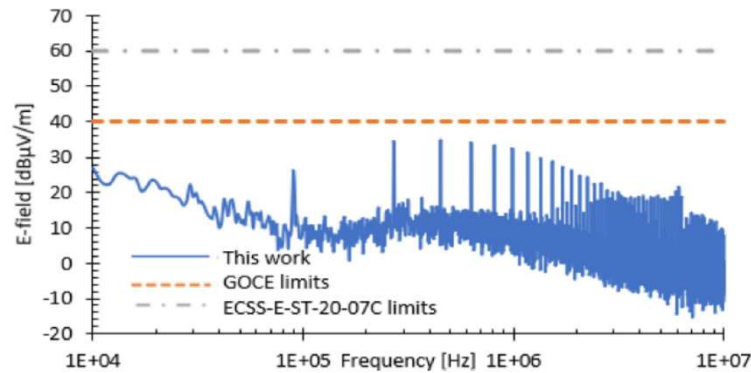
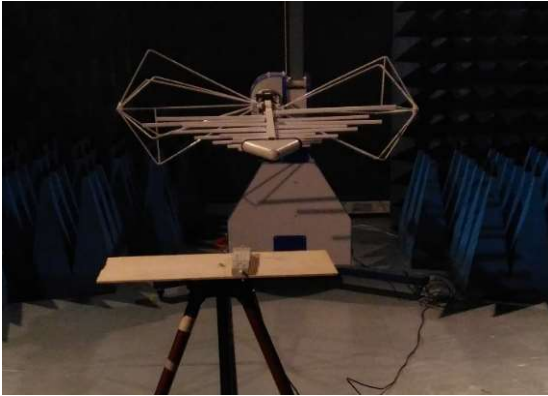
HV-MOS multiple parallel devices, activated according to a proper sequence



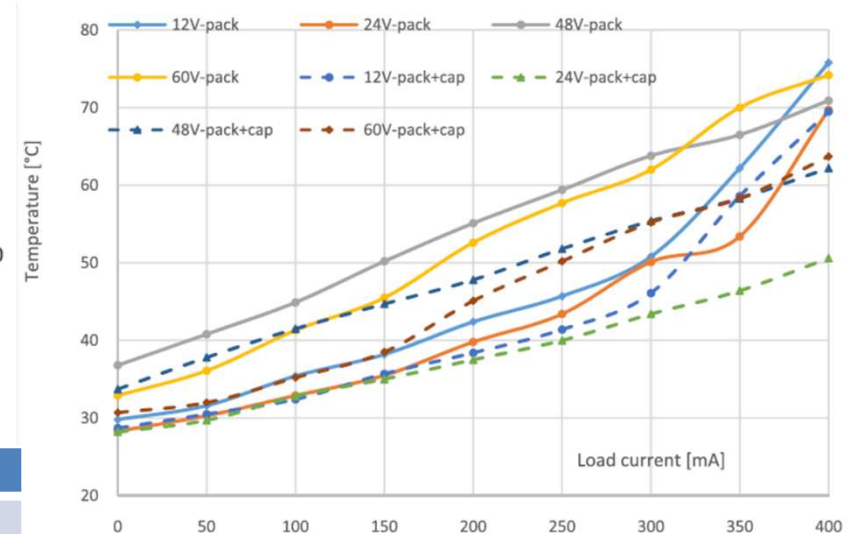
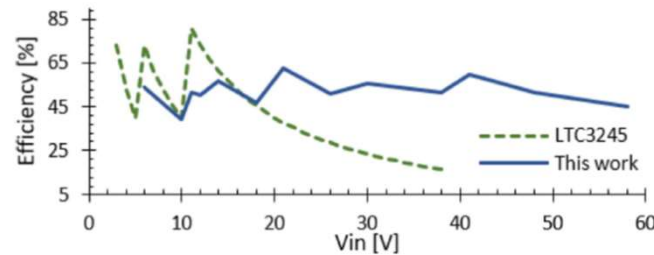
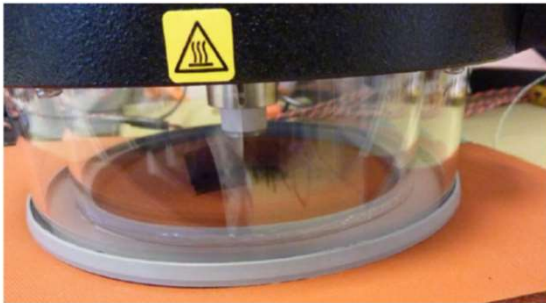
Without soft-start chip damaged by high current peaks at device start

	Conducted EMI reduction	Radiated EMI reduction	Could be integrated	Low design effort	Low cost
EMI filter	+++	-	--	--	--
SKIP control	++	++	+++	+	++
Soft-Start technique	+	+	+++	-	+

EMI, temperature and rad tests



Failure test of the INSUL stage using Si28 with LET = 8.8 Mev·cm²/mg and flux = 20 kions/s.



	This Work	PT4660	LT3245	LM5170
Type	SC+linear	Inductive	SC	Inductive
In-Out insulation	Yes	Yes	No	No
Input range [V]	57*	39	35	79
PSRR [dB]	-60	Off-chip LDO needed		
Output voltage [V]	1.65 / 5	3.3 / 5	5	12 / 48
Max load current [A]	0.4	30	0.25	5
Rad-hard TID	43 krad	N/A	N/A	N/A
Stand-by current [μA]	5	5000	4	10

Inductorless DC/DC Converter for Aerospace Applications With Insulation Features, IEEE TCAS2, 2020

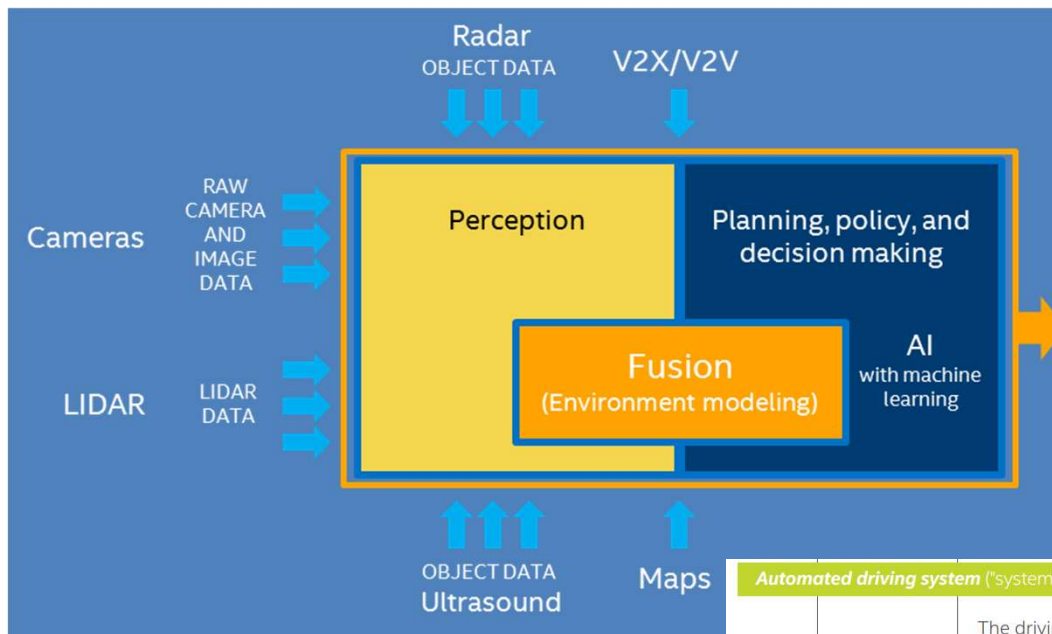
Electrical, Electromagnetic, and Thermal Measurements of 2-D and 3-D Integrated DC/DC Converters”, IEEE Tra. IM 2018

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Context-awareness vehicle perception

Autonomous vehicle perception based on multi-sensor fusion (VideoCameras, Lidar, Radar, Ultrasounds) + fusion with V2X data



Automated driving system ("system") monitors the driving environment						
3	Conditional Automation	The driving mode-specific performance by an automated driving system of all aspects of the dynamic driving task with the expectation that the human driver will respond appropriately to a request to intervene	System	System	Human Driver	Some Driving Modes
4	High Automation	The driving mode-specific performance by an automated driving system of the dynamic driving task, even if a human driver does not respond appropriately to a request to intervene	System	System	System	Some Driving Modes
5	Full Automation	The full-time performance by an automated driving system of all aspects of the dynamic driving task under all roadway and environmental conditions that can be managed by a human driver	System	System	System	All Driving Modes

Context-awareness vehicle perception



Radar (Master of Motion Measures)

Active EM sensor (e.g. 24&77 GHz, 10 dBm). Robust in harsh conditions.

250 m range, 0.1m limited accuracy. *Real-time DSP on FPGA for Radar imaging*

Highly Integrated Low-Power Radars, Artech Book, 2014

Radar-on-Chip/in-Package in Autonomous Driving Vehicles and Intelligent Transport Systems: Opportunities and Challenges. IEEE Sign Pr. Mag 2019

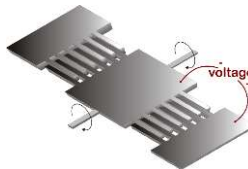
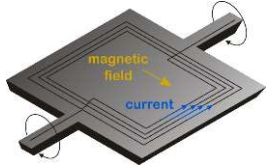


Lidar (Master of 3D mapping), use still limited by cost

Active Light sensor. Mid Range up to 100 m, good accuracy (0.02 m and

0.1⁰ accuracy). *Micromirror scanning proposal for low-cost & wide FOV*

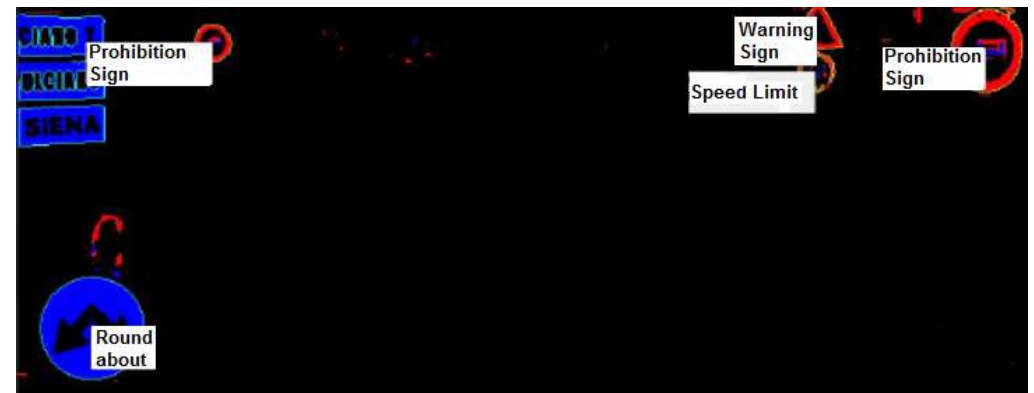
Is Consumer Electronics Redesigning Our Cars?: Challenges of Integrated Technologies for Sensing, Computing, and Storage, IEEE Cons. Eletcr. Mag 2018



Camera (Master of Classification)

Passive. See colors & textures. Cheap. IR sensors needed for night vision

JRTIP2016 640x480 automotive camera & FPGA, recognition at 15 m, <100 ms



Real-time transport-surveillance Radar

X-band Radars for harbor surveillance information system & for railway-crossing and parking or road crossing safety

- Detection & tracking of ships/yachts ingress/egress up to 1.5 km
- Obstacle detection on a railroad or urban road crossing up to 200 m
- Network of Radars for large port areas (increase the covered area)
- Up to 4 Radar nodes for high SIL (Safety Integrity Level) in automated railroad crossing
- 1 Tx + 3 Rx for speed, distance, angle estimation
- Custom microwave board for imaging sensor front-end in X-band
- Real-time DSP on FPGA for power efficiency/compact size

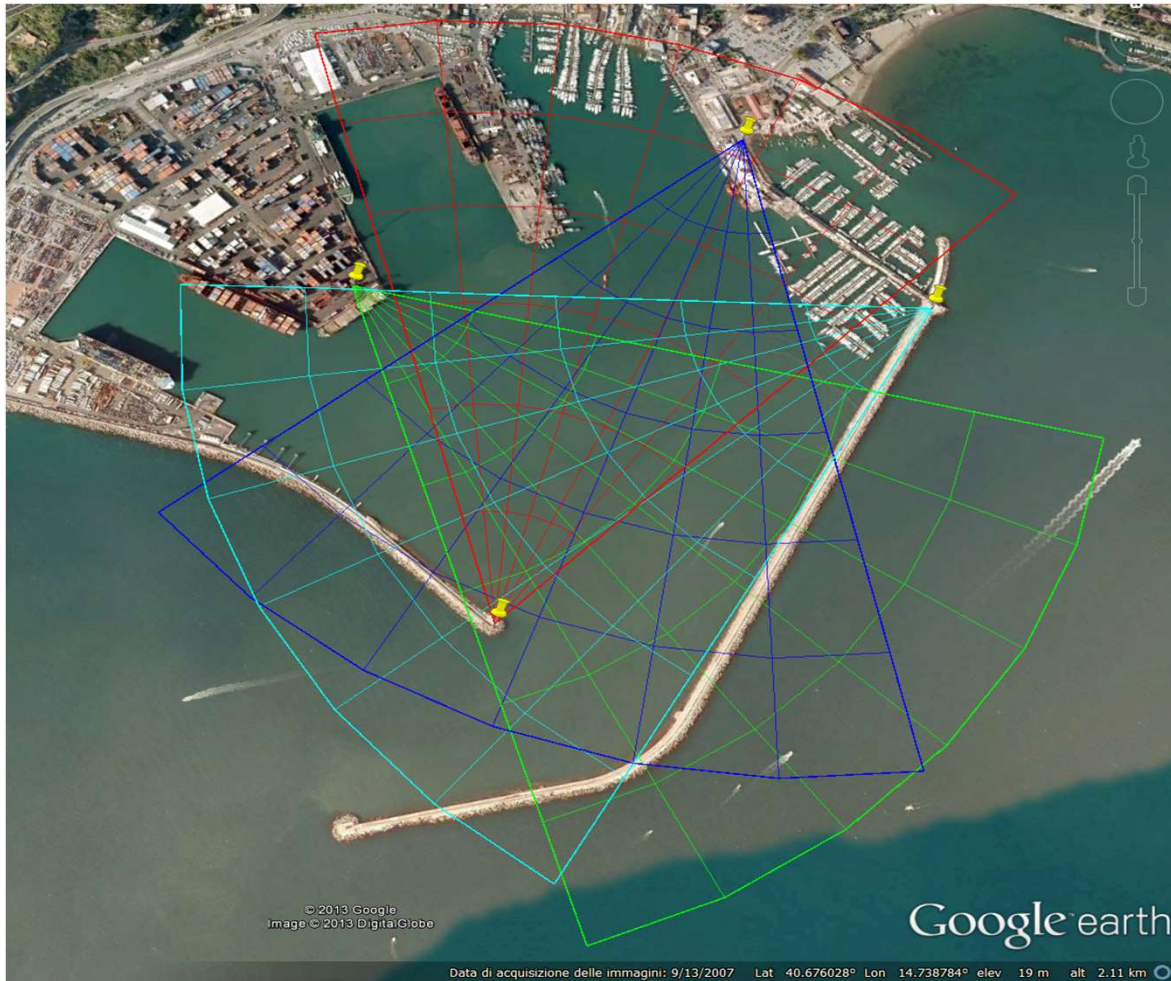
Collaboration with CNIT/RASS (Berizzi, Martorella, Lischi, Massini) & IDS



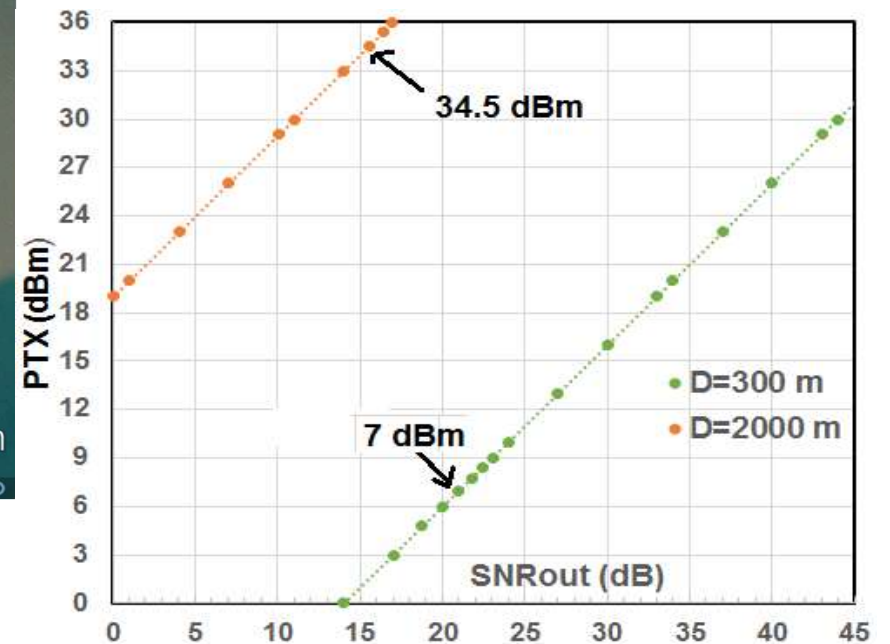
National Inter-University Consortium
for Telecommunications of Italy



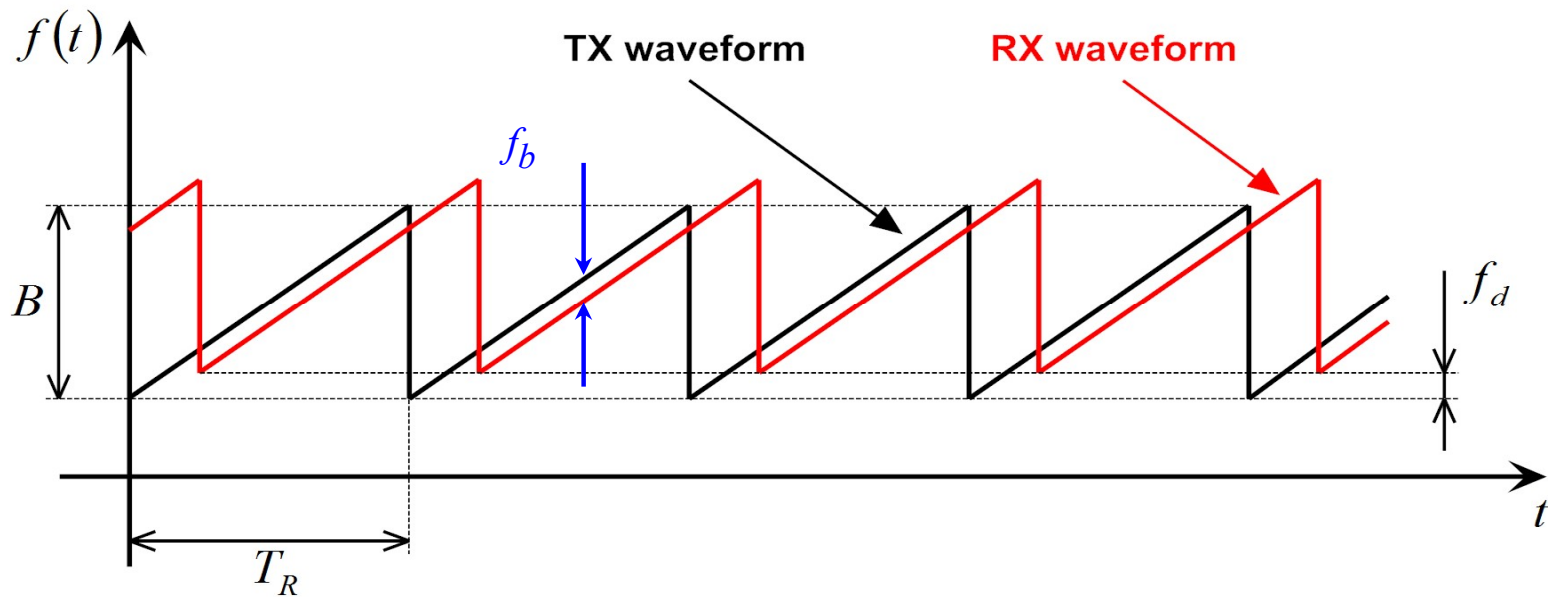
Specification for a transport-surveillance Radar



Max. distance coverage	300 m, 2000 m
Range resolution	40 cm
Max speed	40 m/s
Target RCS	$\approx 1 \div 10^4 \text{ m}^2$
SNR after DSP	> 15 dB



FMCW waveform: moving target



For a moving target:

$$R(t) \cong R_0 + v_r t$$

Doppler frequency:

$$f_d = -\frac{2v_r}{\lambda_0}$$

Range frequency:

$$f_r = \alpha \tau = \frac{B}{T_R} \frac{2R_0}{c}$$

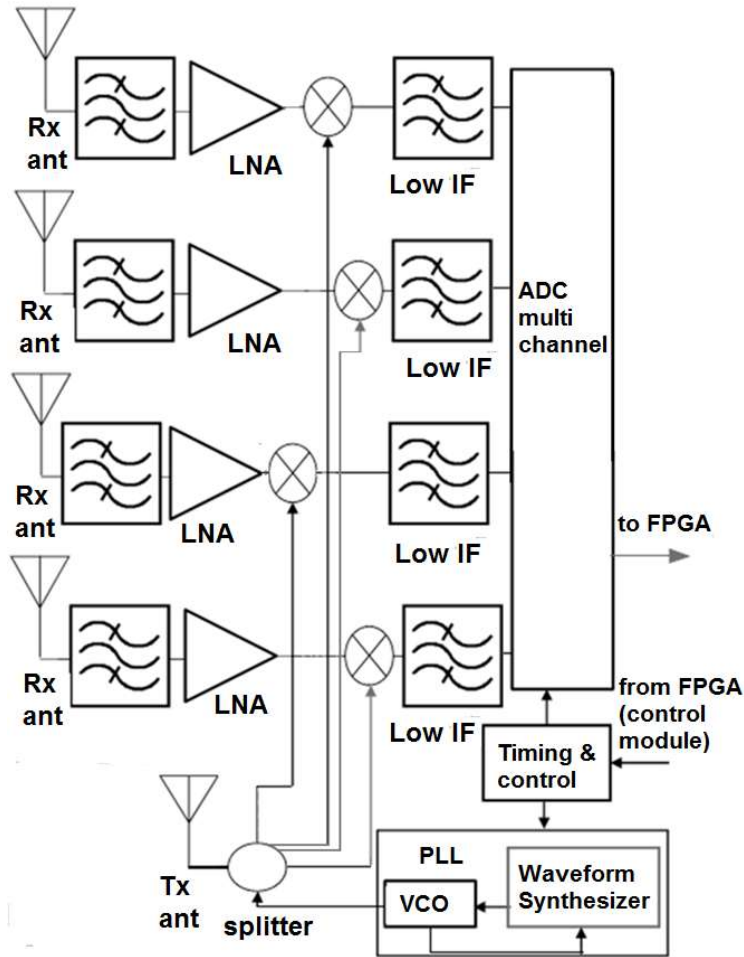
Beat frequency:

$$f_b = f_r + f_d$$

Range-Doppler
coupling effect

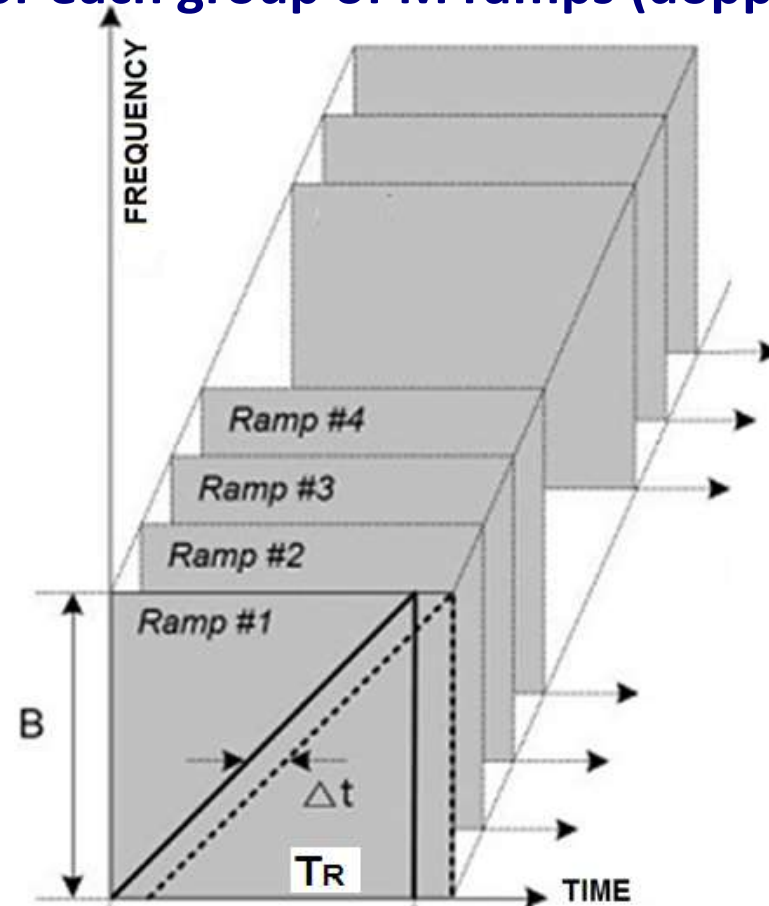
X-band Radar transceiver architecture

Scalable number of RX channels



2D FFT frequency analysis

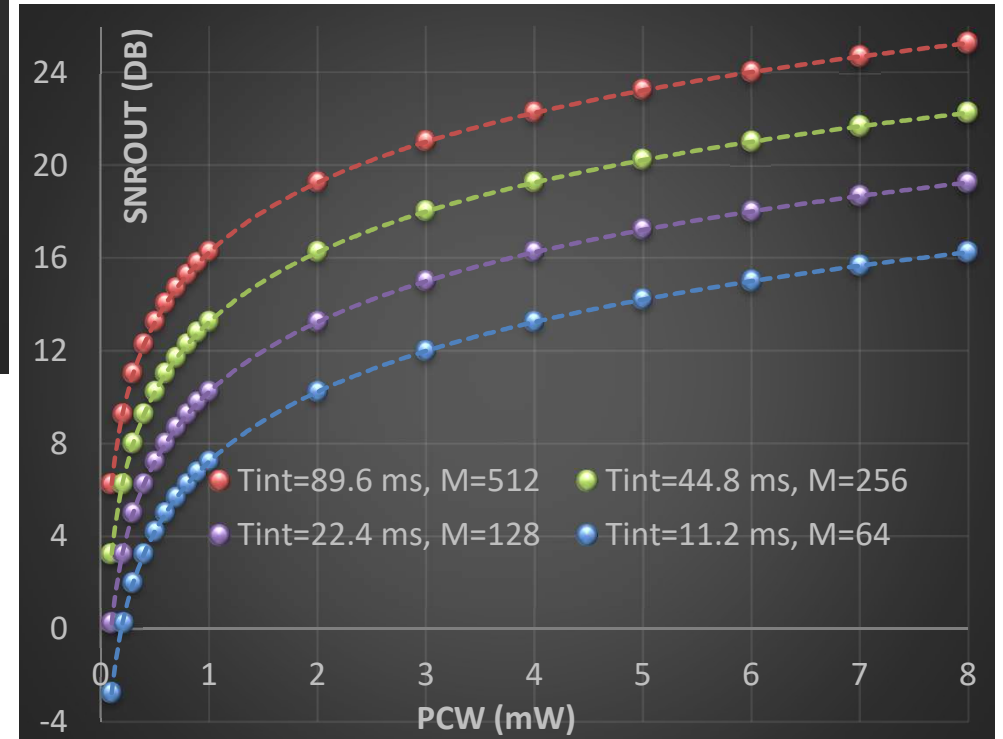
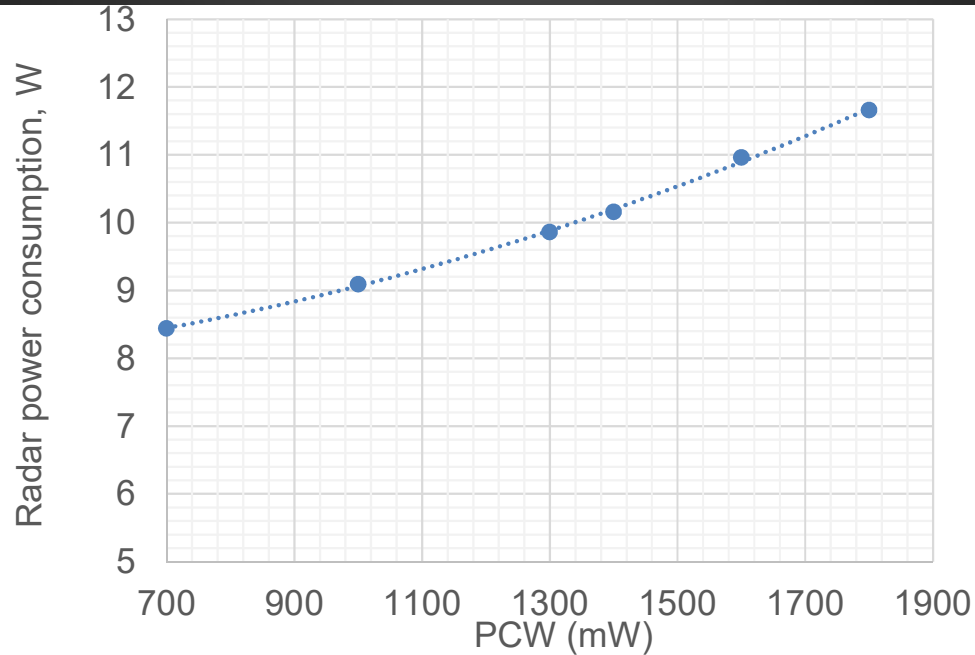
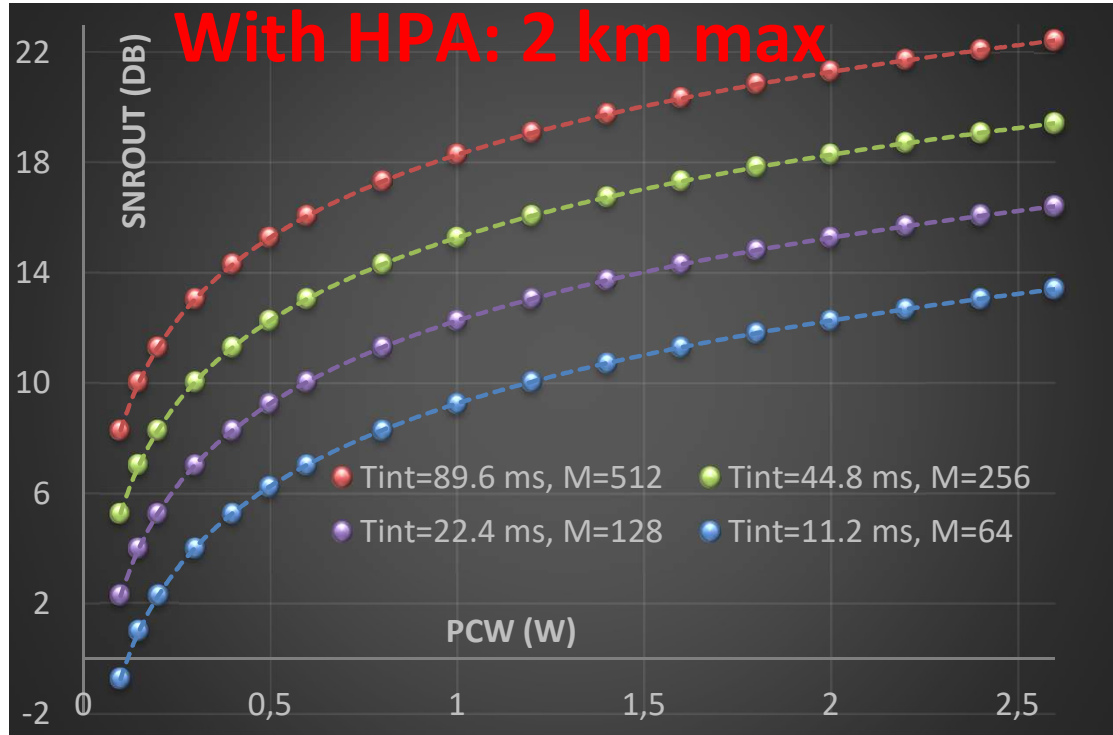
- for each sweep (range)
- for each group of M ramps (doppler)



High-power stage HPA (34.5 dBm P_{cw}) to reach 2 Km

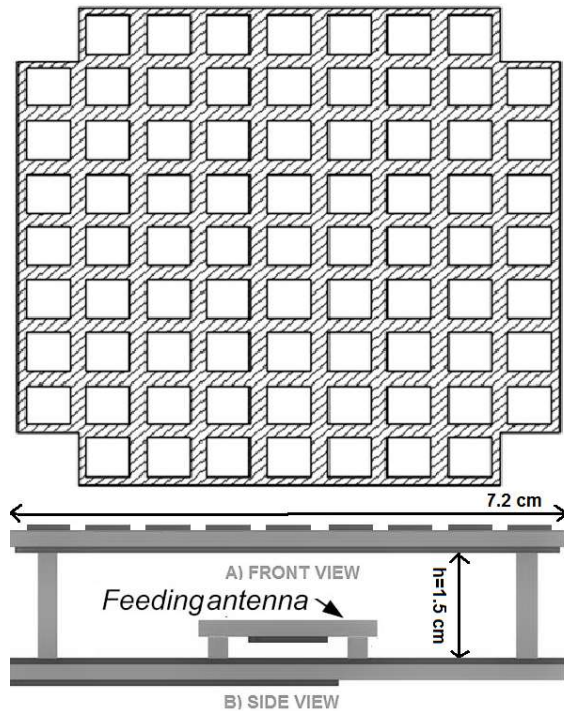
HPA by-passed (7 dBm P_{cw}) for low-power applications with 300 m target

Received SNR vs. P_{cw}



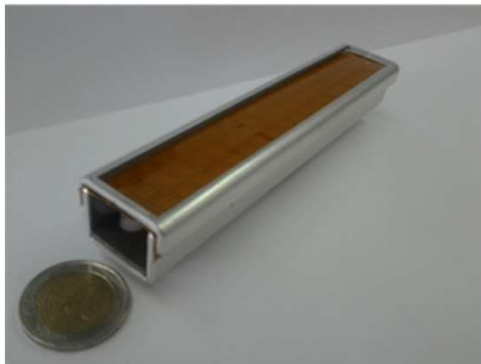
Without HPA: 300 m max

Fabry-Perot resonating antenna

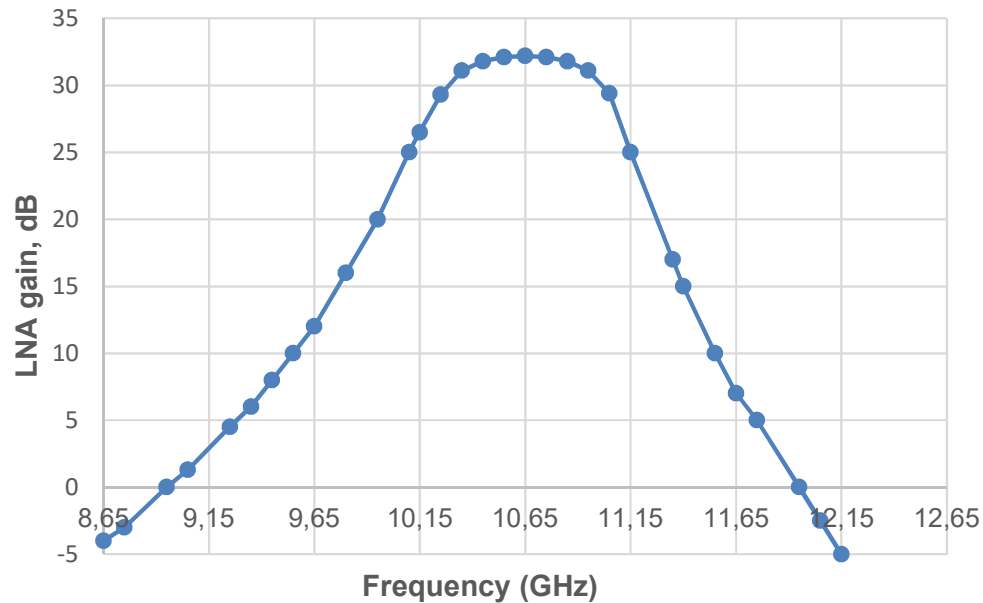


Central frequency	10.65 GHz
Bandwidth	300 MHz-500 MHz
Transmitted power	up to 33 dBm
System losses	8 dB
Noise figure	4.2 dB
SFDR	65 dBc
Sampling frequency	Up to 46 MS/s
ADC resolution	12 bit/14 bit
Antenna technology	Fabry-Perot resonator
Antenna polarization	H-linear
Antenna azimuth HPBW	60°
Antenna elevation HPBW	20°
Antenna gain	13 dBi
Receiving channels	1 to 4

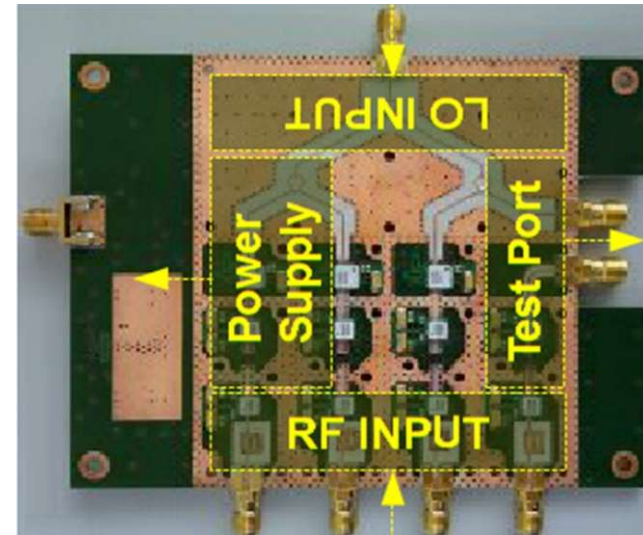
Prototype developed by the Electromagnetic fields and microwaves Lab. of the Department of Information Engineering of the University of Pisa.



Receiver with COTS LNA (from Hittite, now Analog Devices) & Microwave Board



Gain (S21) of the LNA and input filter

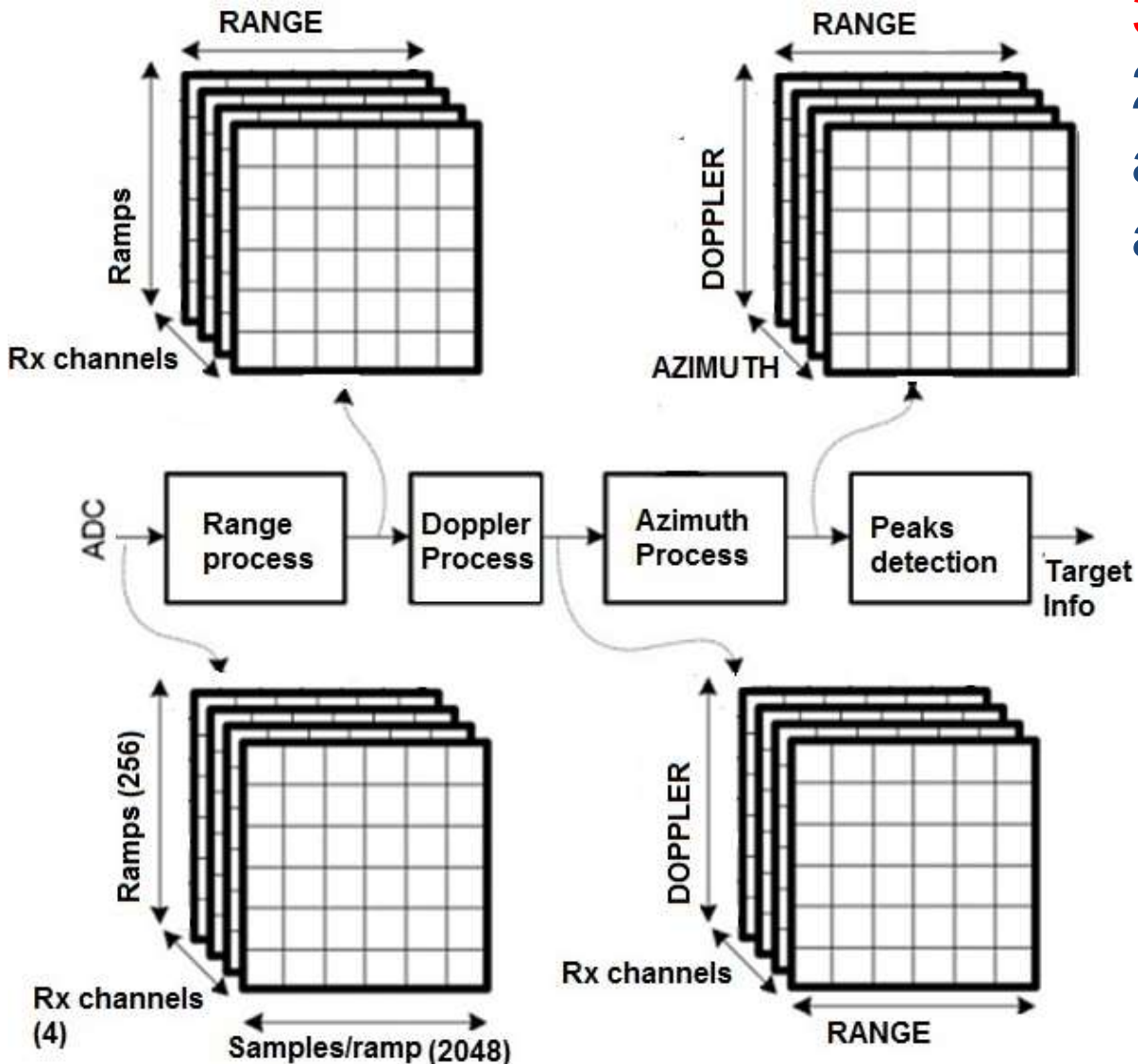


Measurement range R affected by channel impairments, HW performance, target cross-section; resolution d_R depends on sweep band B (4 cm for 77-81 GHz LRR)

$$R = 4 \sqrt{\frac{P_{CW} \lambda^2 G_{ant}^2}{(4\pi)^3} \frac{1}{L} \frac{\sigma}{SNR_{dig}} \frac{1}{k_B T N_F \Delta f}}$$

$$d_R = c / 2B$$

FPGA-based signal processing

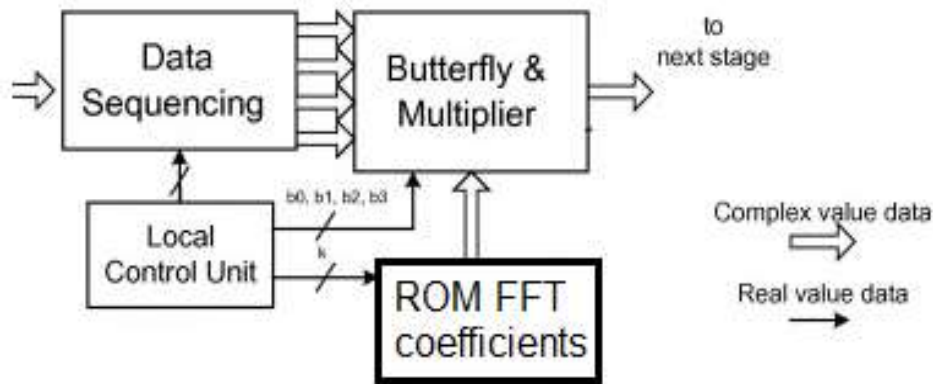


3D FFT range-Doppler:
2D FFT processing + 3rd FFT
along the 4 RX channels for
azimuth and peak estimation

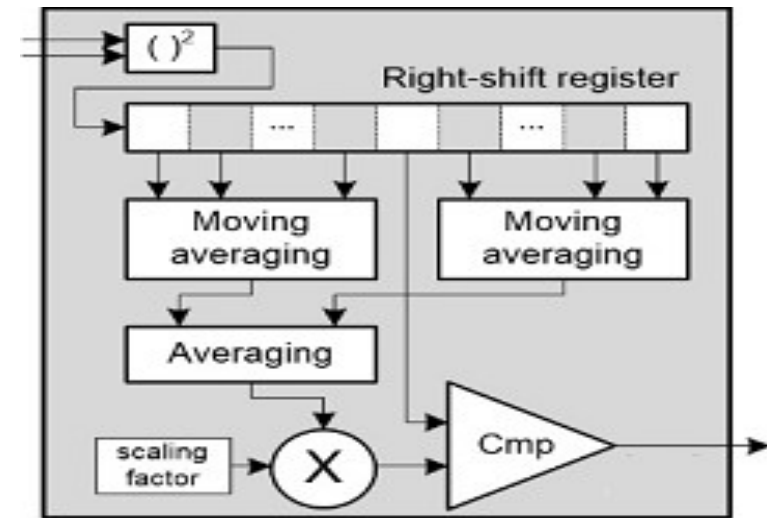
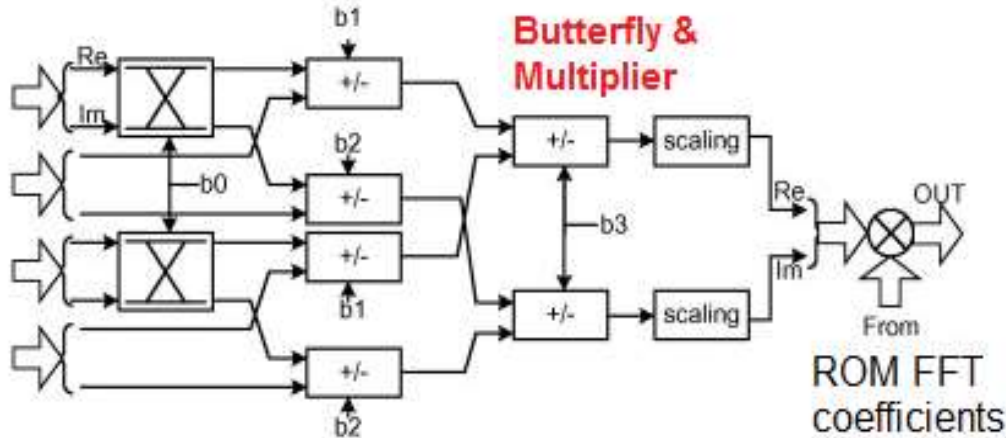
Memory storage:
2M words of 24 bits
(12 bits Re & Im data)

Memory buffering since
data transfer & storage
may become the
bottleneck

HDL blocks for FPGA-based signal processing



FFT core based on a multi Radix-4 stages

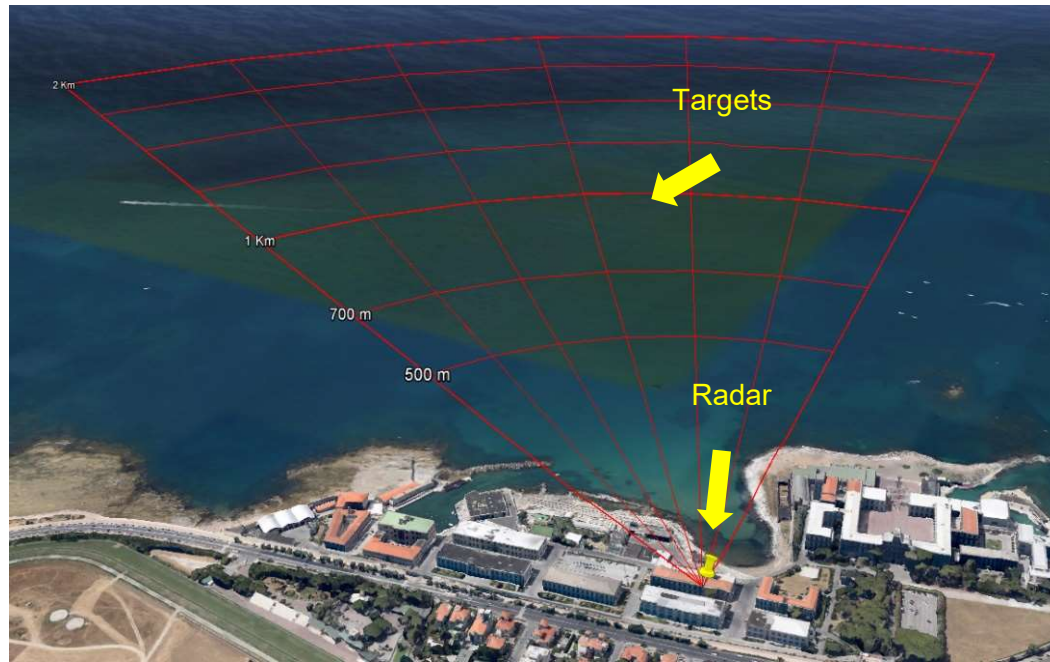


CA-CFAR HDL circuit

Device	FF	DSPslice	LUTs	Mem block	RX Channels
XA7A100T	32.4%	88.3%	35.6%	96%	4
Zynq-XA7Z020	40.9%	93.7%	45.7%	93%	4

Artix-7 FPGA and Zynq FPSoC

Experimental setup and Measurements



Experimental setup for the NATO-SET196 trials, Istituto Vallauri, Livorno, Italy.



A. Length: 32.5m, Width: 6.47m
• Material: wood and iron



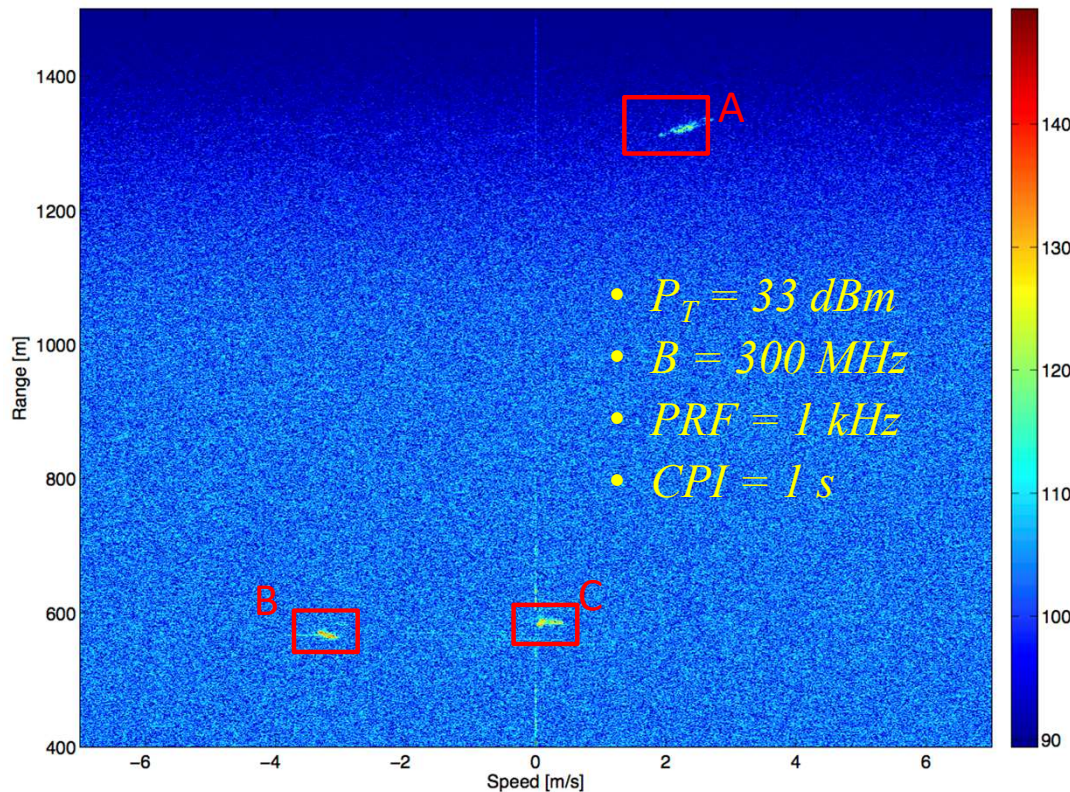
B. Length: 8.5m, Width: 2.3m
• Material: fiberglass and iron



C. Length: 13.20m, Height: 13m
• Material: wood

Targets & Range-Doppler map

	Freq, GHz	Type	Power cost	Range, Output power	Channels
This work	10.3-10.8	FMCW	< 8 W	300 m@5 mW, 1.5 km@2W	5
IEEE TBSC	3.1-10.6	Pulsed UWB	73 mW	<1 m, 7 pJ/pulse	2
MOTL 2013	22-26	Pulsed UWB	N/A	N/A, 2 mW	2
TERMA2015	9.375	Pulsed	N/A	45 km @ 32 kW	N/A
EURAD2014	10.5-10.8	FMCW	>100 W	1.2 km@2 W	3
IEEETIM 2014	2.48 - 2.56	FMCW	N/A	20-100m @ 100 mW	N/A
AMS2013	9.4	FMCW	650 W	50 km@100W	1



Radar sensor signal acquisition and multi-dimensional FFT processing for surveillance applications in transport systems, IEEE Trans IM 2017

Design of compact and low-power X-band Radar for mobility surveillance applications, Computer and Electr., Engineering, 2016

Hardware accelerator IP cores for real-time Radar and camera-based ADAS", Journal RT Image Proc. 2020

Detected targets appear like an oval due to the target physical size and to Radar resolution limits in distance and speed

A post-processing step on the range-doppler image allows extracting size along radial axis and speed

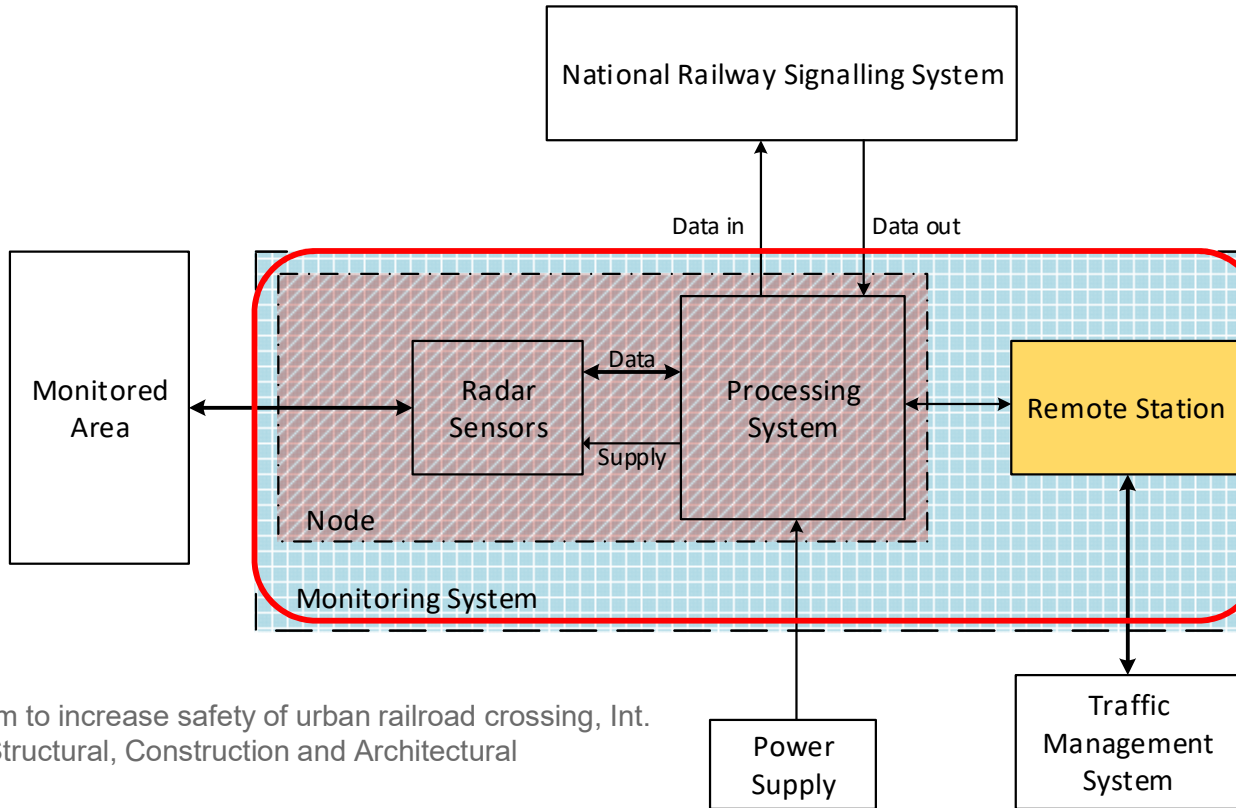
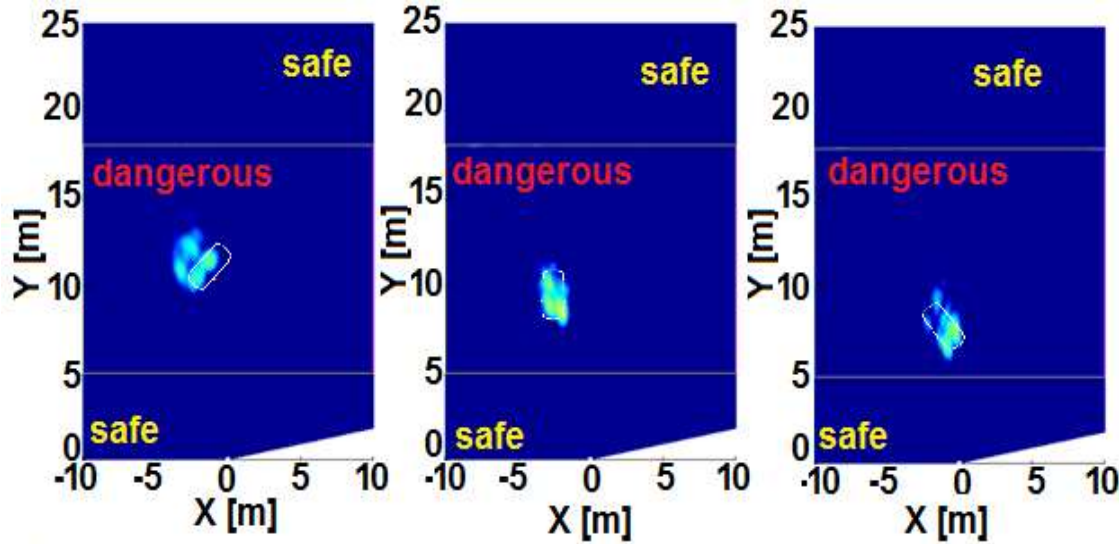
Example of installation on a roadcrossing



Safety Integrity Level SIL4

Railway surveillance-radar configuration

Thanks to
R. Piernicola, IDS

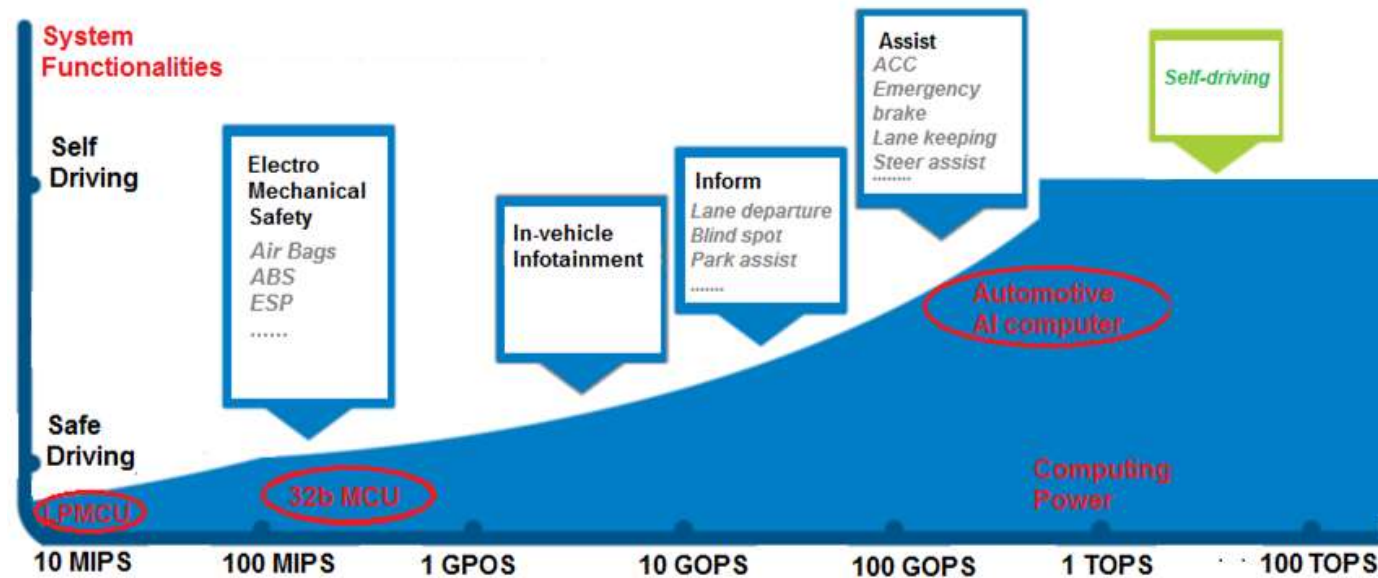


Outline

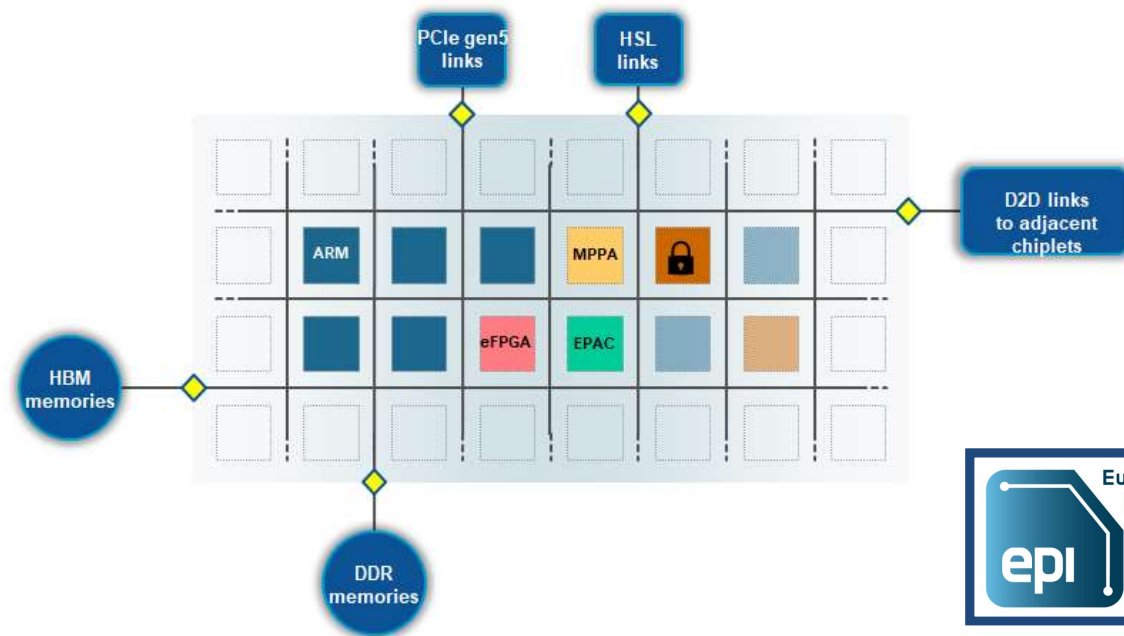
- Trends in smart vehicles & intelligent transport systems (ITS) and impact for society/economy
- University pillars: opportunities for continuous education, R&D, and technology transfer in Electronics
- **Example R&D case studies:**
 - Integrated Power Converters for 48 V micro/mild-hybrid vehicles
 - ITS surveillance X-band Radar
 - **Cybersecurity acceleration**



ADAS needs eHPC

Recent advances and trends in on-board embedded and networked automotive systems, IEEE Transactions Industrial Informatics, 2018



NVIDIA Xavier claims 30 TOPS, Drive AGX Pegasus 160 TOPS, Tesla FSD 144 TOPS







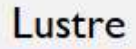




































- EPAC - EPI Accelerator 
- MPPA - Multi-Purpose Processing Array 
- eFPGA - embedded FPGA 
- Cryptographic HW & SW (EU Sovereignty) 



EPI RHEA chip (Multi-core ARM64b with SVE in 6 nm technology)



EPI partners & HW/SW eco-system

   <p>Full HPC Environment for the Reference Platform</p>  	    <p>Co-design exploration space</p>    	   <p>Automotive eHPC software support</p>    	 <p>Programming tools & Libraries: LLVM/GCC with OpenMP; OpenMPI; FFTW; BLIS; OpenBLAS,...</p>   
<p>Security, Low-level software, power management</p>  		   <p>Linux Operating System</p>    	
     <p>EPI Processor</p>		<p>EPI Reference Hardware</p>   	



Automotive cybersecurity: a real challenge



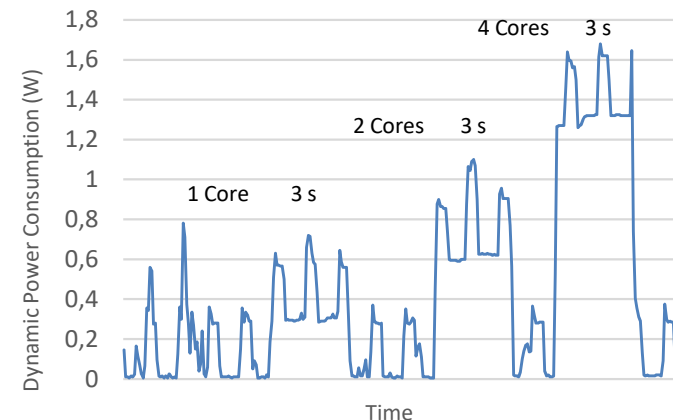
Exposure to attacks: Vehicle hack, Data tampering, Denial of Service
 SW computing of crypto functions slow and power demanding

Performances data for SHA-2 256 and ECDSA SW implementation (Open SSL library on 4-core 64b Cortex-A53 Broadcom MPSoC)

Number of core	Exec. time (s)	D (Mb)	TH (Mbps)	P (mW)	E (mJ/Mb)
1	3	917.4	305.80	300	0.98
2	3	1812.8	604.27	600	0.99
4	3	3628	1209.33	1300	1.07

Number of core	Exec. time (s)	D (Op)	TH (Op/s)	P (mW)	E (mJ/Op)
1	10	282.4	28.24	310	10.98
2	10	560	56	620	11.07
4	10	1085	108.5	1330	12.26

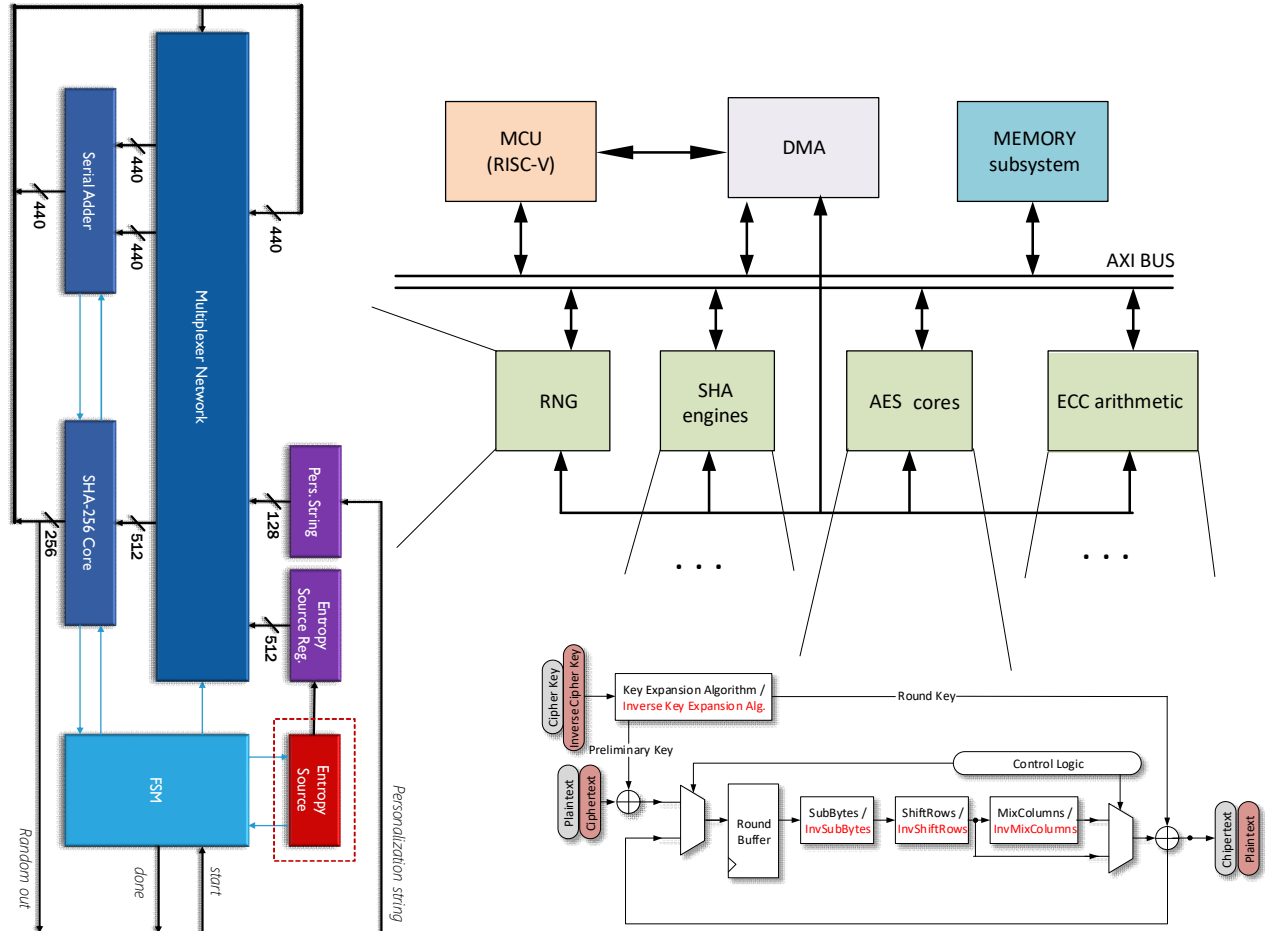
Crypto accelerators for power-efficient and real-time on-chip implementation of secure algorithms", IEEE ICECS 2019



3 orders of magnitude in speed/power improvement with HW acceleration

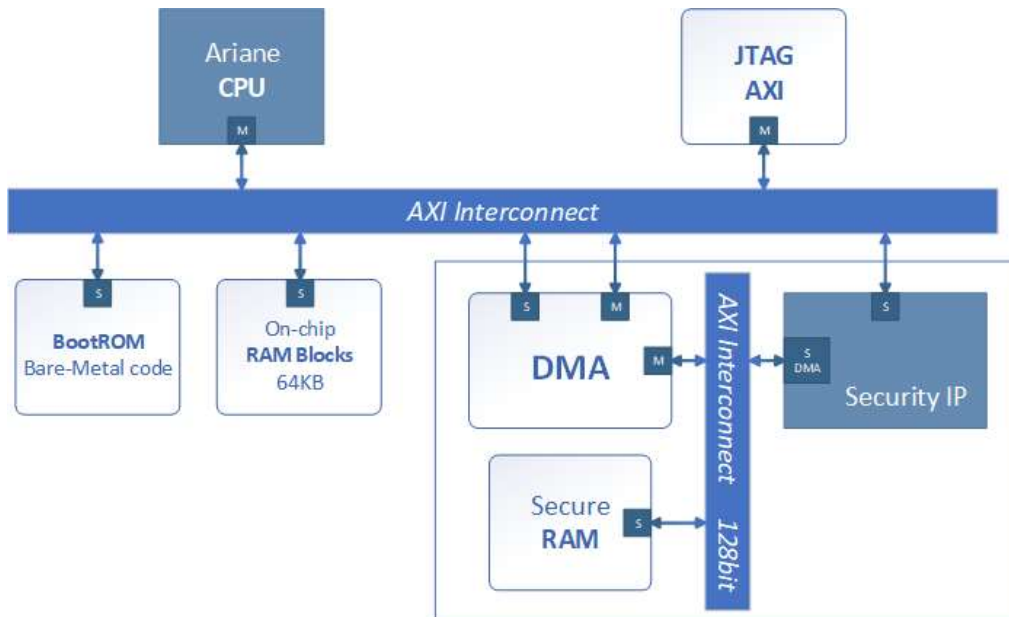
HW-based Root of trust

- Definition of the HW and SW architecture of the Secure Element (SE) that will be the root of a trusted chain to avoid that malicious SW runs on EPI multi-cores
- The multi-core on-chip system divided in secure zones (quadrants) each with a secure MCU
- Focus on a secure boot sequence and on the relation between secure elements and power manager
- SE trustiness by proper HW/SW partitioning including: OTP/e-fuse integration, RNG for seed generation, acceleration for advanced and complex crypto functions, programmability (e.g. RISC-V plus DMA capability)



Configurable HW crypto IPs

- Up to 300 Gbps AES XTS encryption/decryption in 7 nm
- Support core security functions needed for diffused security standard such as SHE, MACSec or WAVE, EVITA full compliant
- Design of accelerator IPs for embedded cybersecurity
 - AES 128/256 with configurable modes (ECB, CBC, CTR, OFB, CFB, CCM, CMAC, GCM, XTS) compliant with NIST SP800-38XX
 - SHA2 & SHA3, 256 and 512 bits compliant with FIPS-180/FIPS-202
 - Configurable ECC-based public key accelerator modes (ECDSA, ECIES, ECDH,..) and curves (NIST-P 256, 521) compliant with FIPS 186-3,...
 - TRNG & CSPRNG verified vs NIST SP800-90B, SP800-22



XCZU7EV (ZCU106)	CLB LUTs	CLB Reg
ARIANE+AES	75696	66710
ECC	77983	47925
SHA	16419	20071
RNG	10689	7374
Misc	6000	2500
Tot	186787	144580
Available	230400	460800
Util [%]	81%	31%

More than just an HW IP core

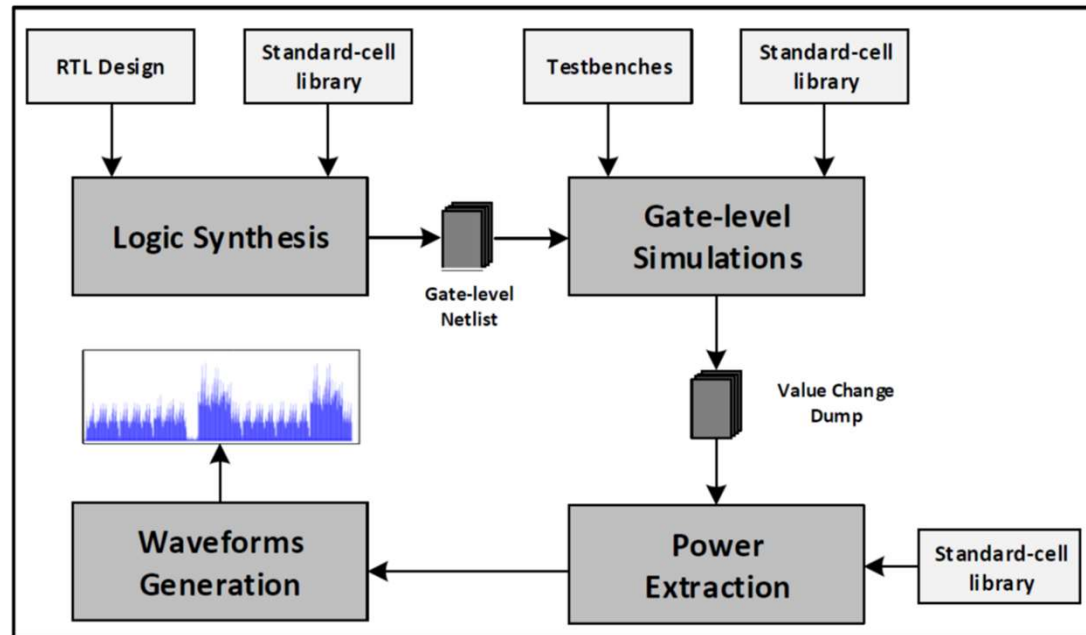
Secure management policy of keys/certificates embedded in HW, enabling advanced SW services

- Enforce good practice in sensitive data management at HW level
- Provide mechanisms at HW level to enforce usage of cryptographic algorithm and associated keys (**key management interface and internal secure storage**)
- Provide necessary robustness to detect and limit impact of SW bugs and attacks by enforcing **strict usage rules** of the crypto processor interface
 - need to know, data separation per usage, and state machine approaches
- Help to architecture the SW for high security and safety, with the concept of **SW islands**: simple and restricted functionality, by isolating the different operations when manipulating sensitive data; limiting access to associated sensitive data to each part
- Ease the certification of the HW/SW by using concept of **independent island when dealing with the configuration of the crypto processor** (locking mechanism, CPU privilege restrictions, ...)
- Crypto-processor configuration and operation management

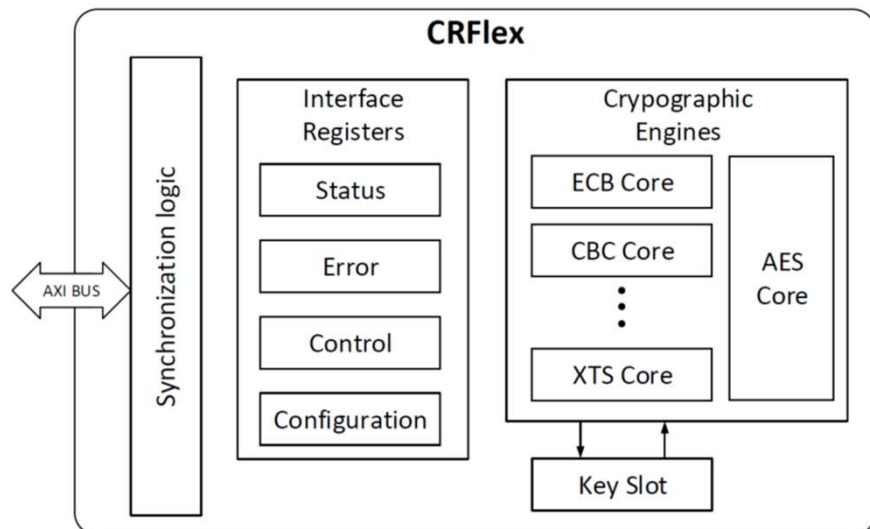
More than just an HW IP core

Design being aware of side-channel attacks:

- Simulating (and measuring) power and EM information leakage
- Design-style to have flat power and EM profiles, particularly during safety critical operations



AES IP design & complexity results



CRFlex module	Slice LUT usage	Slice Register usage
AES Core	23 %	17 %
ECB Core	0.2 %	0.4 %
CBC Core	0.3 %	7 %
CFB Core	1 %	7 %
OFB Core	0.3 %	0.6 %
CTR Core	0.2 %	4 %
CMAC Core	2 %	4 %
GCM Core	43 %	17 %
CCM Core	10 %	8 %
XTS Core	3 %	2 %
Interface registers	9 %	8 %
Synchronization logic	8 %	25 %

Slice LUTs and Registers occupation for each CRFlex sub-module on Xilinx Zynq-7000.

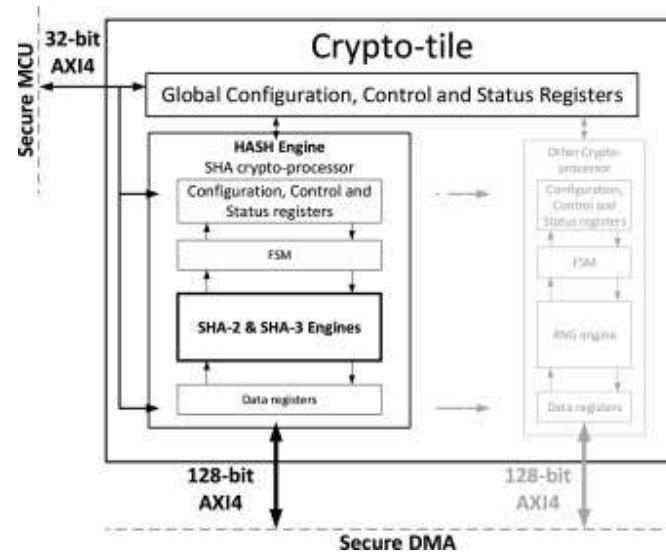
Cipher Mode	Confidentiality	Integrity	Authenticity
AES-ECB	✓	✗	✗
AES-CBC	✓	✗	✗
AES-OFB	✓	✗	✗
AES-CFB	✓	✗	✗
AES-CTR	✓	✗	✗
AES-CMAC	✗	✓	✗
AES-GCM	✓	✓	✓
AES-CCM	✓	✓	✓
AES-XTS	✓	✗	✗

7 nm ASIC at 0.75 V 85 °C

AES-ECB-256		
# Stage(s)	Logic Usage	Throughput
1 Stage	28 kGE	27.4 Gbps
2 Stages	55.7 kGE	55 Gbps
7 Stages	195 kGE	192 Gbps
14 Stages	370 kGE	384 Gbps

SHA3/SHA-2 IP engine

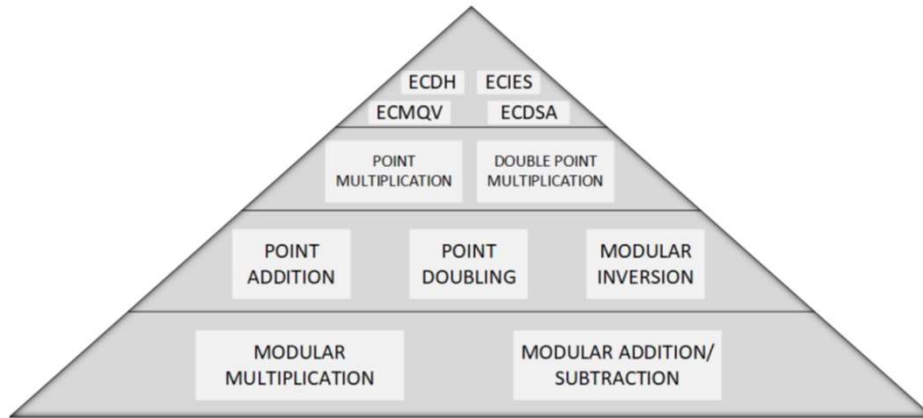
SHA2 and SHA-3 accelerator design in a 7 nm technology within the European Processor Initiative, Microprocessors and Microsystems, 2020



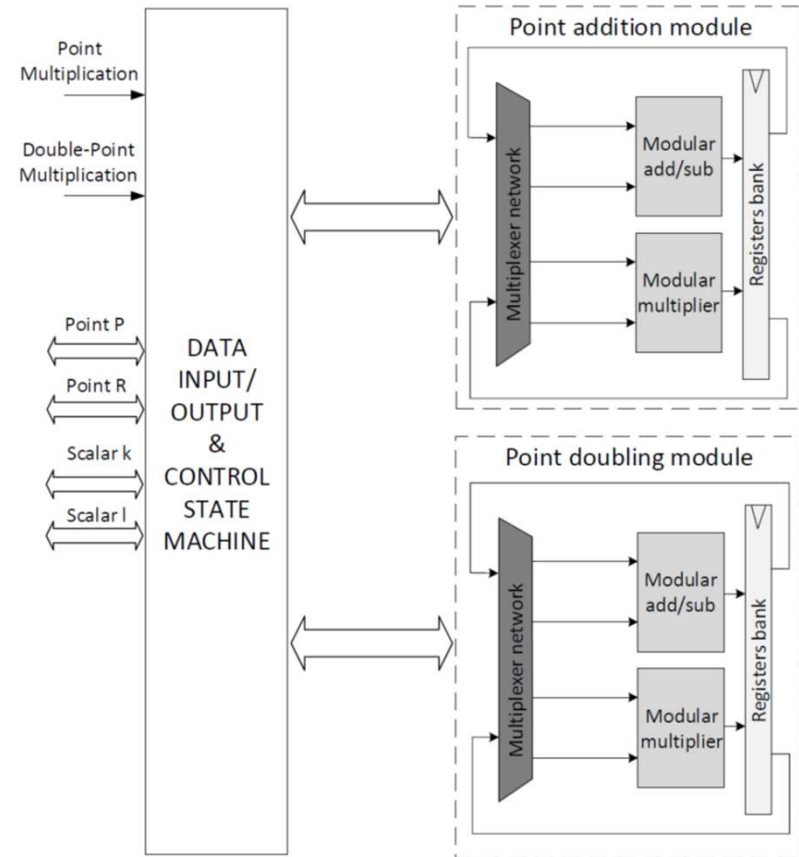
SHA-3/SHA2 in 7 nm ASIC 0.75 V 85 °C (SHA-3 @ max 5GHz, SHA2 @ max 4.35 GHz)

Operation	Latency [Clk cycles]	Throughput [Gbps]	Operation	Area, kGE SHA-3	Area, kGE SHA2	Power, mW SHA-3	Power, mW SHA2
SHA2 224	67	33.24	224	31.27	15.43	24.96	13.43
SHA2 256	67	33.24	256	31.55	15.45	25.29	13.45
SHA2 384	83	53.67	384	31.36	28.28	25.07	22.56
SHA2 512	83	53.67	512	30.74	29.93	25.67	24.66
SHA-3 224	25	230.40	256-224	31.65	15.47	25.19	13.47
SHA-3 256	25	217.60	384-256	31.93	31.33	24.03	21.47
SHA-3 384	25	166.40	384-224	32.47	31.14	24.80	21.67
SHA-3 512	25	115.20	512-384	32.17	30.32	27.54	24.97
			512-256	31.85	31.26	26.18	21.47
			512-224	32.11	31.35	25.73	21.44
			384-256-224	32.21	31.19	25.41	21.46
			512-256-224	32.33	31.42	26.33	21.51
			512-384-224	32.21	31.62	25.58	21.68
			512-384-256	33.07	31.92	23.18	21.69
			512-384-256-224	33.43	31.79	25.29	21.70

ECC IP engine



Fast and configurable elliptic curve crypto-processor on 7 nm technology, Microprocessors and Microsystems, 2021

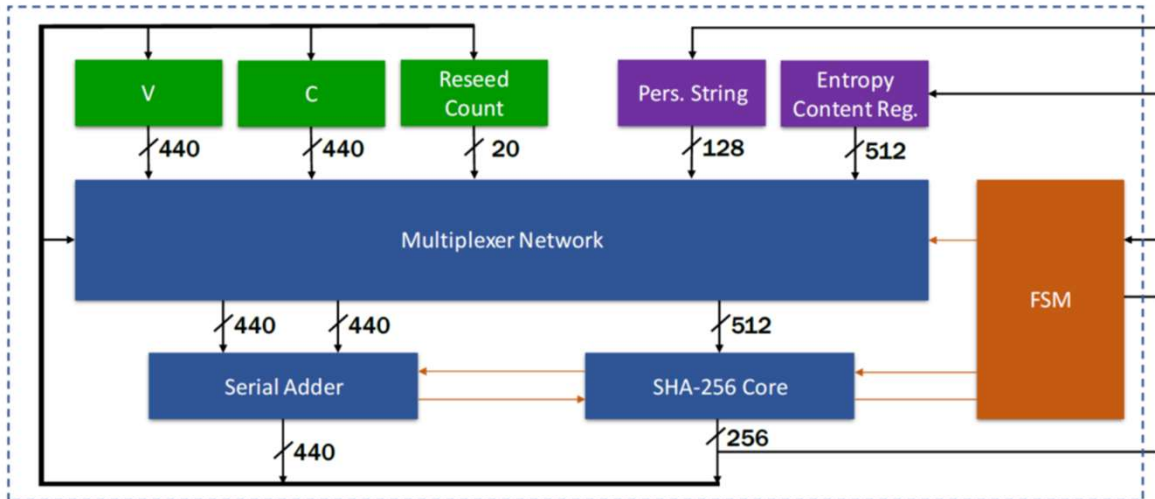


7 nm ASIC at 0.75 V 85 °C

Configuration	Technology	Gate counts (kGE)	Kcycles	Freq. (MHz)	T(us)
P-256 only	45 nm	281	36.390	400	90.975
P-521 only	45 nm	407	254.456	375	686.54
P-256/-521	45 nm	447	36.390/257.456	375	97.04/686.54
P-256 only	7 nm	279	36.390	1820	19.99
P-521 only	7 nm	405	257.456	1650	156.03
P-256/-521	7 nm	445	36.39/257.456	1650	22.05/156.03

CSPNRG IP engine

the 7 nm Artisan ASIC standard-cell reaches a throughput value of 19.67 Gbps, given a maximum clock frequency of 5.15 GHz, requiring an overall complexity of 46.56 kGE.



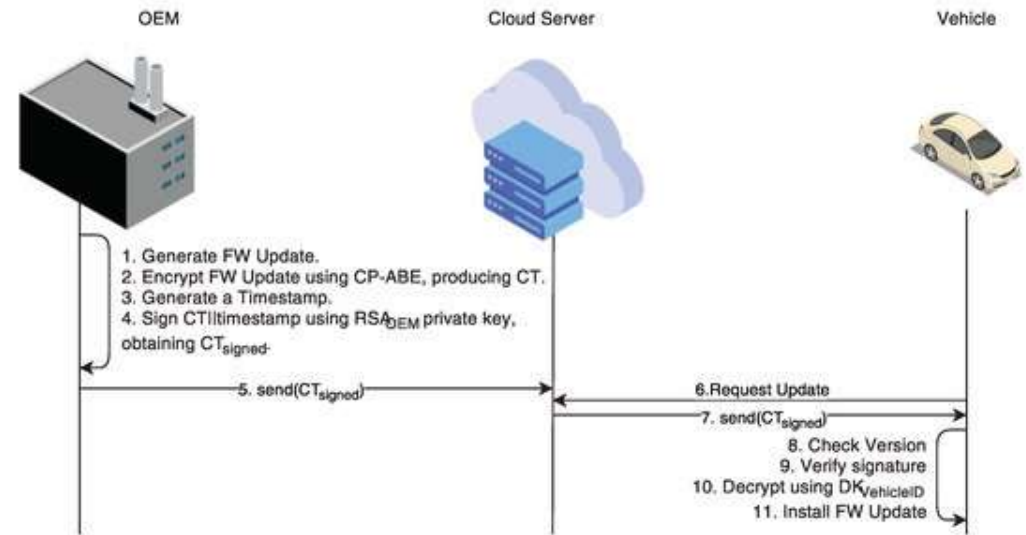
- Two Entropy seed options:
- external seed
 - on-chip TRNG made of a mix of Fibonacci and Galois digital Ring-Oscillators

Test	Block/Template Length	Pass Rate
Frequency (Monobit)	-	0.9924
Frequency Within a Block	256	0.9876
Runs	-	0.9901
Longest-Run-of-Ones in a Block	-	0.9878
Binary Matrix Rank	-	0.9901
Discrete Fourier Transform (Spectral)	-	0.9874
Non-overlapping Template Matching	10	[0.9801-0.9974]
Overlapping Template Matching	10	0.9848
Maurer's Universal Statistical	-	0.9901
Linear Complexity	1024	0.9900
Serial	16	0.9825, 0.9876
Approximate Entropy	10	0.9901
Cumulative Sums (Cusums)	-	0.9901
Random Excursions	-	[0.9826-0.9947]
Random Excursions Variant	-	[0.9875-0.9975]

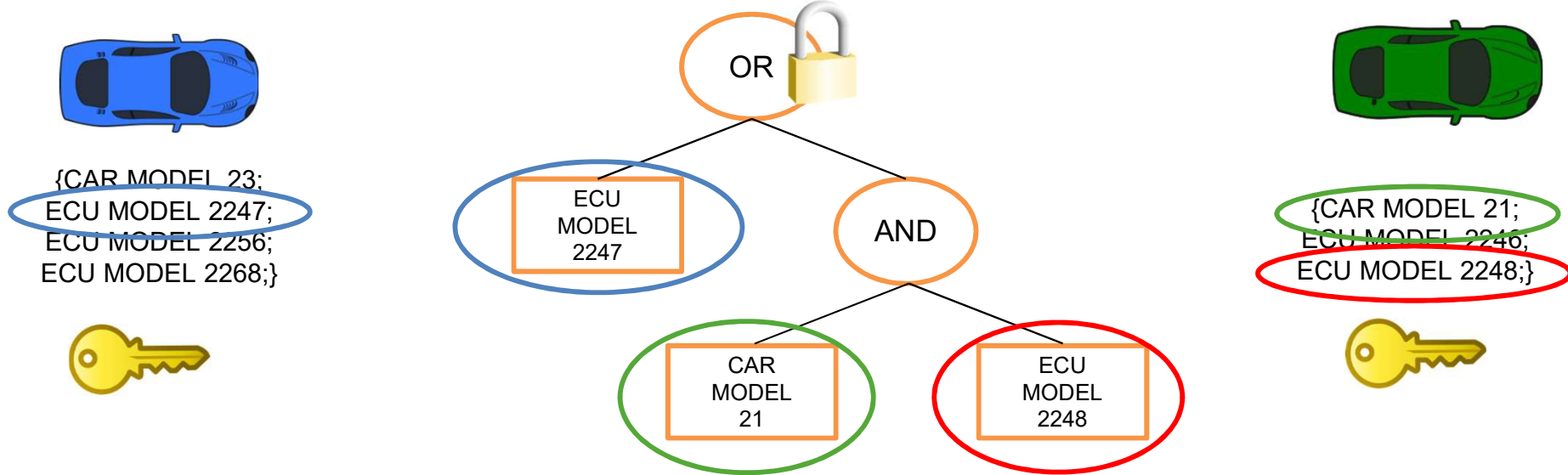
NIST Statistical Test Suite parameters and results

ABE Over The Air (OTA) SW/FW UPDATE

Attribute Based Encryption (ABE) is an asymmetric key encryption scheme that allows one to embed an Access Control Mechanism inside a ciphertext by means of a Policy, which is a Boolean expression upon some values, called attributes



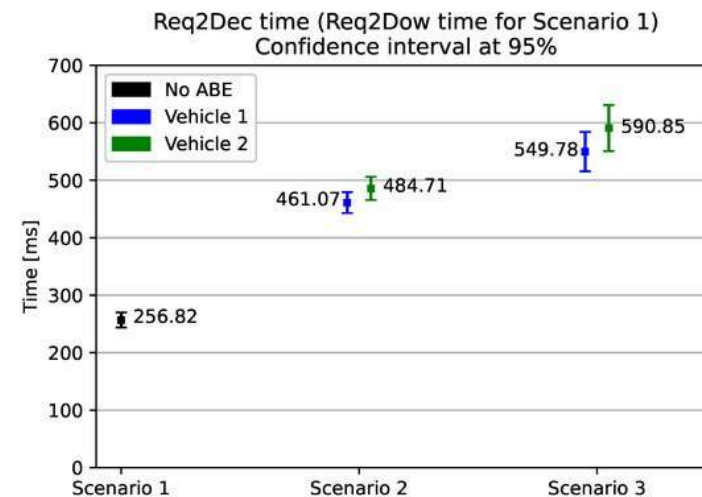
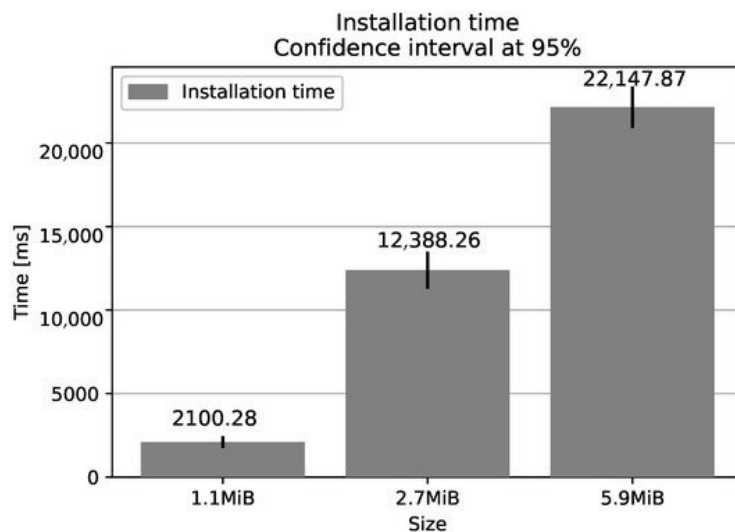
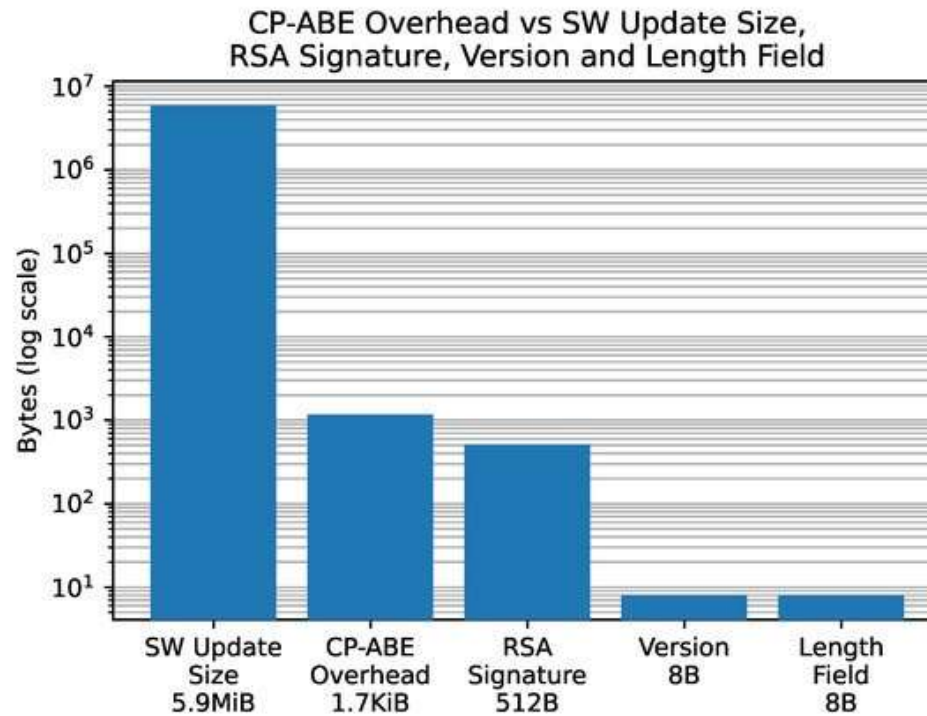
«The more attribute you *need* to decrypt a ciphertext, the more operations you must perform»



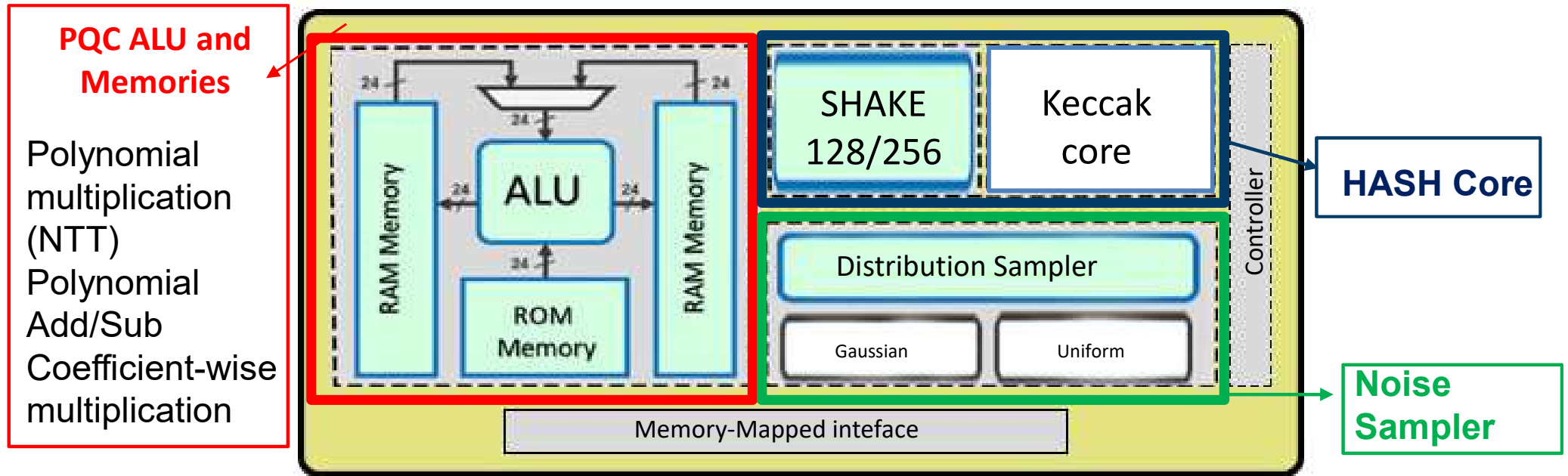
IDEA: FW/SW updates are encrypted in such a way only authorized ECUs can decrypt them
ADVANTAGE: encrypted FW/SW updates can transit or rest on untrusted cloud servers

ABE OTA overhead

Performance evaluation of attribute-based encryption in automotive embedded platform for secure software over-the-air update, Sensors 2021



PQC Lattice Hardware accelerator



HW acceleration allows x 300 gain vs SW solution

Prototype and test on ZCU106

70 kGE + 1 MB and 0.6 GHz in 45nm

Block name	Max freq	CLB LUTs	CLB reg	BRAM	DSP
ALU+Memories	300 MHz	1882	4399	14,5	8
NOISE SAMPLER	370 MHz	227	532	0	4
SHAKE	750 MHz	5642	2969	0	0
TOTAL	300 MHz	8627	4713	14,5	12

Conclusions



- Vehicular electronics: **high impact** on society and fast growing trends in digital and electrified vehicles & intelligent transport systems (ITS)
- **Opportunities** from **reskilling** needs (continuous learning), upgrade of Electronics University teaching offer
- **Huge scientific R&D field** (Horizon Europe, PNRR)
- Technology transfer and consulting opportunities
- Spin-off in related fields (robotics, energies, avionics, ...)
- Challenge: effort to **go beyond the classic EE comfort zone**

Thanks for your attention



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<https://www.linkedin.com/in/sergio-saponara-3031431/>

<https://www.youtube.com/watch?v=Bg8zw1SWiJA&feature=youtu.be>

Sistemi elettronici per mobilità intelligente

<https://www.youtube.com/watch?v=2Y7uLbpehcQ&list=PL13CyHsHfOt1GC19RsPv-FvITnbbnd2e0&index=7>

Integrated Serializer and High-speed driver for multi-gbps And Rad-Hard links

